HEATHKIT
CONTINUING
EDUCATION

Individual Learning Program

MICROPROCESSORS

Appendix B

DATA SHEETS

EE-3401

Courtesy of
Motorola Semiconductor
Products, Inc

CONTENTS

MOTOROLA Semiconductors
3501 ED BLUESTEIN BLVD AUSTIN TEXAS 78721

MC6808

Advance Information

MICROPROCESSOR WITH CLOCK

The MC6808 is a monolithic 8-bit microprocessor that contains all the registers and accumulators of the present MC6800 plus an internal clock oscillator and driver on the same chip.

The MC6808 is completely software-compatible with the MC6800 as well as the entire M6800 family of parts. Hence the MC6808 is expandable to 65K words.

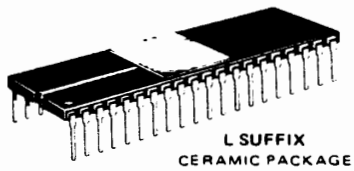
This very cost-effective MPU allows the designer to use the MC6808 in consumer as well as industrial applications without sacrificing industrial specifications.

- On-Chip Clock Circuit
- Software-Compatible with the MC6800
- Expandable to 65K words
- Standard TTL-Compatible Inputs and Outputs
- 8-Bit Word Size
- 16-Bit Memory Addressing
- Interrupt Capability

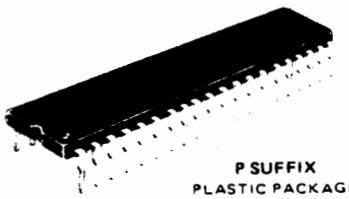
MOS

(N-CHANNEL, SILICON-GATE, DEPLETION LOAD)

MICROPROCESSOR WITH CLOCK

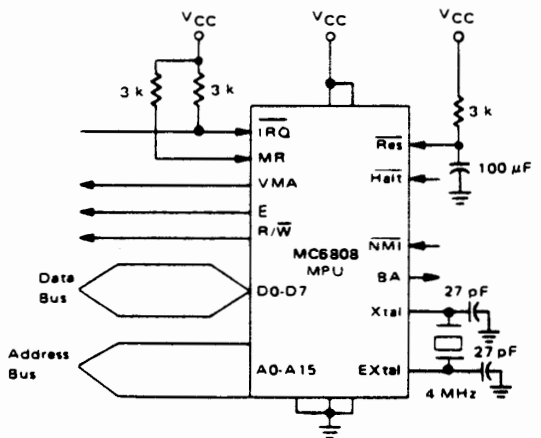


L SUFFIX
CERAMIC PACKAGE
CASE 715

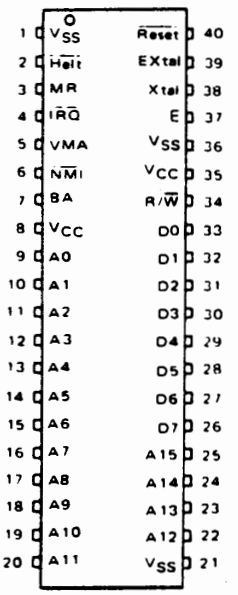


P SUFFIX
PLASTIC PACKAGE
CASE 711

FIGURE 1 – TYPICAL MICROPROCESSOR INTERFACE



PIN ASSIGNMENT



MOTOROLA Semiconductors
BOX 20912 • PHOENIX, ARIZONA 85036

MC6800

(0 to 70°C; L or P Suffix)

MC6800C

(-40 to 85°C; L Suffix only)

MICROPROCESSING UNIT (MPU)

The MC6800 is a monolithic 8-bit microprocessor forming the central control function for Motorola's M6800 family. Compatible with TTL, the MC6800, as with all M6800 system parts, requires only one +5.0-volt power supply, and no external TTL devices for bus interface.

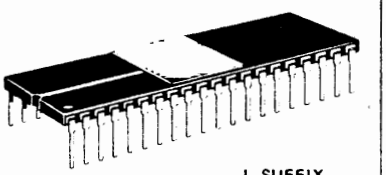
The MC6800 is capable of addressing 65K bytes of memory with its 16-bit address lines. The 8-bit data bus is bidirectional as well as 3-state, making direct memory addressing and multiprocessing applications realizable.

- Eight-Bit Parallel Processing
- Bi-Directional Data Bus
- Sixteen-Bit Address Bus – 65K Bytes of Addressing
- 72 Instructions – Variable Length
- Seven Addressing Modes – Direct, Relative, Immediate, Indexed, Extended, Implied and Accumulator
- Variable Length Stack
- Vectored Restart
- Maskable Interrupt Vector
- Separate Non-Maskable Interrupt – Internal Registers Saved In Stack
- Six Internal Registers – Two Accumulators, Index Register, Program Counter, Stack Pointer and Condition Code Register
- Direct Memory Addressing (DMA) and Multiple Processor Capability
- Clock Rates as High as 1 MHz
- Simple Bus Interface Without TTL
- Halt and Single Instruction Execution Capability

MOS

(N-CHANNEL, SILICON-GATE)

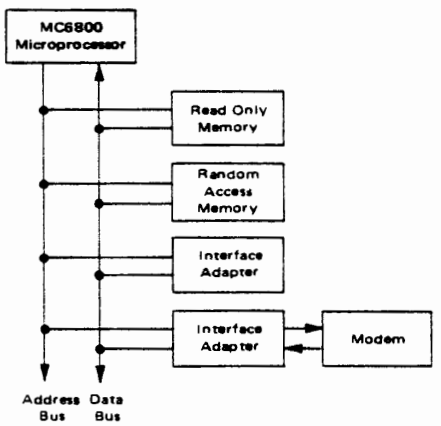
MICROPROCESSOR



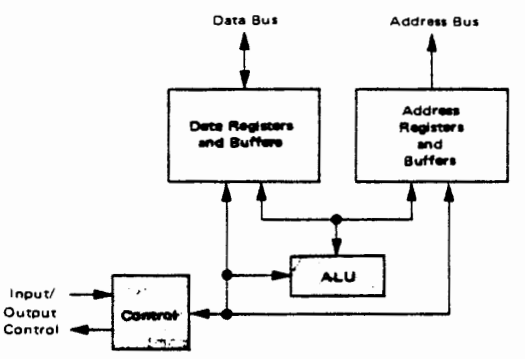
L SUFFIX
CERAMIC PACKAGE
CASE 715

NOT SHOWN: P SUFFIX
PLASTIC PACKAGE
CASE 711

M6800 MICROCOMPUTER FAMILY
BLOCK DIAGRAM



MC6800 MICROPROCESSOR
BLOCK DIAGRAM



MC6800

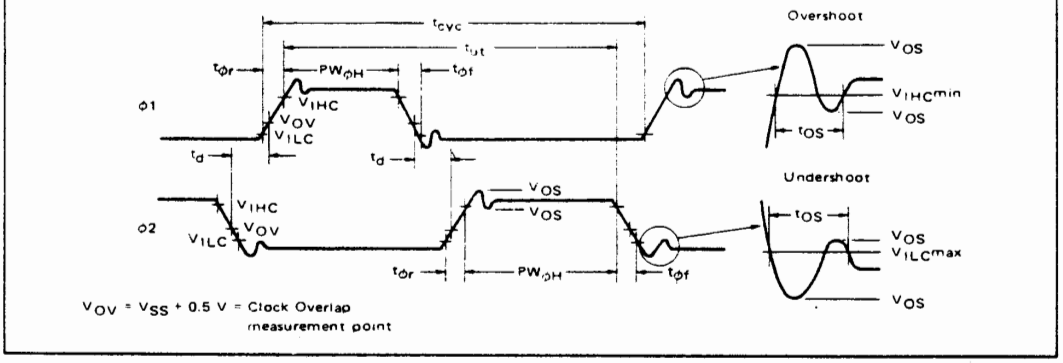
ELECTRICAL CHARACTERISTICS (V_{CC} = 5.0 V ± 5%, V_{SS} = 0, T_A = 0 to 70°C unless otherwise noted.)

Characteristic		Symbol	Min	Typ	Max	Unit
Input High Voltage	Logic	V_{IH}	V_{SS} + 2.0	–	V_{CC}	Vdc
	ϕ1,ϕ2	V_{IHC}	V_{CC} – 0.3	–	V_{CC} + 0.1	
Input Low Voltage	Logic	V_{IL}	V_{SS} – 0.3	–	V_{SS} + 0.8	Vdc
	ϕ1,ϕ2	V_{ILC}	V_{SS} – 0.1	–	V_{SS} + 0.3	
Clock Overshoot/Undershoot – Input High Level		V_{OS}	V_{CC} – 0.5	–	V_{CC} + 0.5	Vdc
– Input Low Level			V_{SS} – 0.5	–	V_{SS} + 0.5	
Input Leakage Current		I_{in}				μAdc
(V_{in} = 0 to 5.25 V, V_{CC} = max)	Logic*		–	1.0	2.5	
(V_{in} = 0 to 5.25 V, V_{CC} = 0.0 V)	ϕ1,ϕ2		–	–	100	
Three-State (Off State) Input Current	D0-D7	I_{TSI}	–	2.0	10	μAdc
(V_{in} 0.4 to 2.4 V, V_{CC} = max)	A0-A15,R/W		–	–	100	
Output High Voltage		V_{OH}				Vdc
(I_{Load} = –205 μAdc, V_{CC} = min)	D0-D7		V_{SS} + 2.4	–	–	
(I_{Load} = –145 μAdc, V_{CC} = min)	A0-A15,R/W,VMA		V_{SS} + 2.4	–	–	
(I_{Load} = –100 μAdc, V_{CC} = min)	BA		V_{SS} + 2.4	–	–	
Output Low Voltage (I_{Load} = 1.6 mAdc, V_{CC} = min)		V_{OL}	–	–	V_{SS} + 0.4	Vdc
Power Dissipation		P_D	–	0.600	1.2	W
Capacitance #	ϕ1,ϕ2	C_{in}	80	120	160	pF
(V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	TSC		–	–	15	
	DBE		–	7.0	10	
	D0-D7		–	10	12.5	
	Logic Inputs		–	6.5	8.5	
	A0-A15,R/W,VMA	C_{out}	–	–	12	pF
Frequency of Operation		f	0.1	–	1.0	MHz
Clock Timing (Figure 1)						
Cycle Time		t_{cyc}	1.0	–	10	μs
Clock Pulse Width		$PW_{\phi H}$				ns
(Measured at V_{CC} – 0.3 V)	ϕ1		430	–	4500	
	ϕ2		450	–	4500	
Total ϕ1 and ϕ2 Up Time		t_{ut}	940	–	–	ns
Rise and Fall Times	ϕ1,ϕ2	$t_{\phi r}$, $t_{\phi f}$	5.0	–	50	ns
(Measured between V_{SS} + 0.3 V and V_{CC} – 0.3 V)						
Delay Time or Clock Separation		t_d	0	–	9100	ns
(Measured at V_{OV} = V_{SS} + 0.5 V)						
Overshoot Duration		t_{OS}	0	–	40	ns

*Except $\overline{IRQ}$ and $\overline{NMI}$, which require 3 kΩ pullup load resistors for wire-OR capability at optimum operation.

#Capacitances are periodically sampled rather than 100% tested.

FIGURE 1 – CLOCK TIMING WAVEFORM



V_{OV} = V_{SS} + 0.5 V = Clock Overlap measurement point

MC6800

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	V_{CC}	−0.3 to +7.0	Vdc
Input Voltage	V_{in}	−0.3 to +7.0	Vdc
Operating Temperature Range	T_A	0 to +70	°C
Storage Temperature Range	T_{stg}	−55 to +150	°C
Thermal Resistance	θ_{JA}	70	°C/W

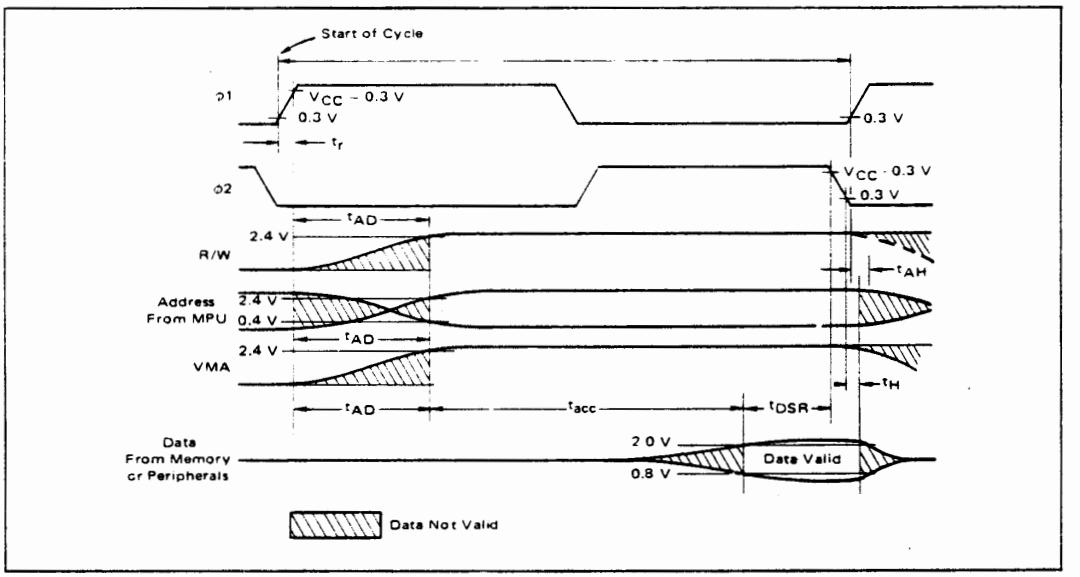
This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

READ/WRITE TIMING Figures 2 and 3, f = 1.0 MHz, Load Circuit of Figure 6.

Characteristic	Symbol	Min	Typ	Max	Unit
Address Delay	t_{AD}	–	220	300	ns
Peripheral Read Access Time $t_{acc} = t_{ut} - (t_{AD} + t_{DSR})$	t_{acc}	–	–	540	ns
Data Setup Time (Read)	t_{DSR}	100	–	–	ns
Input Data Hold Time	t_H	10	–	–	ns
Output Data Hold Time	t_H	10	25	–	ns
Address Hold Time (Address, R/W, VMA)	t_{AH}	50	75	–	ns
Enable High Time for DBE Input	t_{EH}	450	–	–	ns
Data Delay Time (Write)	t_{DDW}	–	165	225	ns
Processor Controls*					
Processor Control Setup Time	t_{PCS}	200	–	–	ns
Processor Control Rise and Fall Time	t_{PCr}, t_{PCf}	–	–	100	ns
Bus Available Delay	t_{BA}	–	–	300	ns
Three State Enable	t_{TSE}	–	–	40	ns
Three State Delay	t_{TSD}	–	–	700	ns
Data Bus Enable Down Time During $\phi 1$ Up Time (Figure 3)	$t_{\overline{DBE}}$	150	–	–	ns
Data Bus Enable Delay (Figure 3)	t_{DBED}	300	–	–	ns
Data Bus Enable Rise and Fall Times (Figure 3)	t_{DBEr}, t_{DBEf}	–	–	25	ns

*Additional information is given in Figures 12 through 16 of the Family Characteristics – see pages 17 through 20.

FIGURE 2 – READ DATA FROM MEMORY OR PERIPHERALS



MC6800

FIGURE 3 – WRITE IN MEMORY OR PERIPHERALS

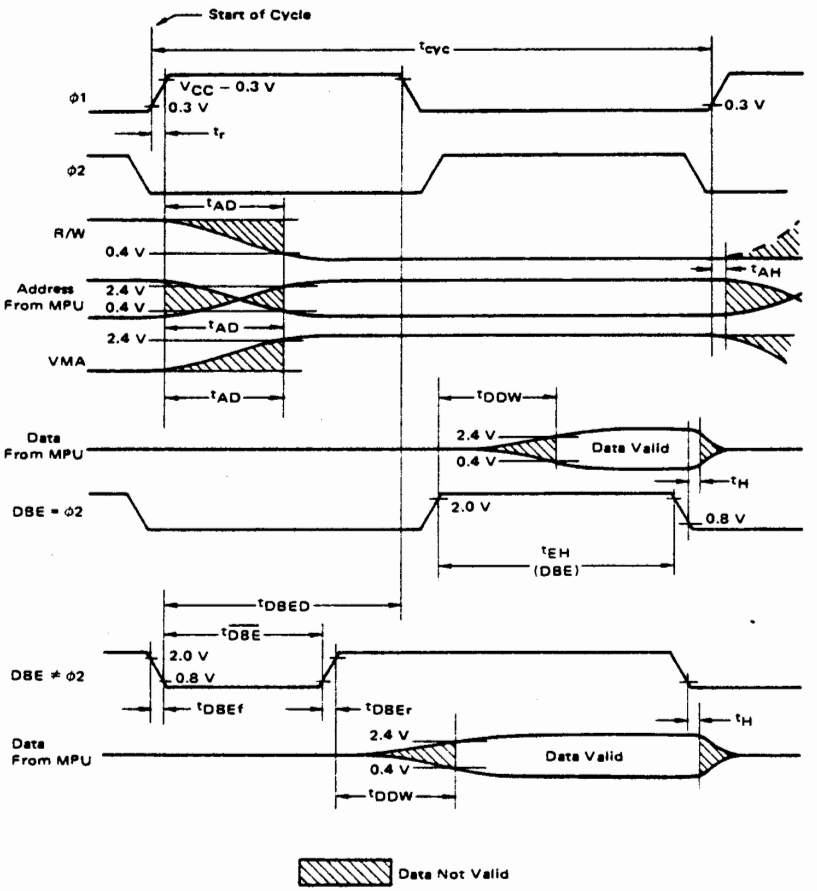


FIGURE 4 – TYPICAL DATA BUS OUTPUT DELAY versus CAPACITIVE LOADING

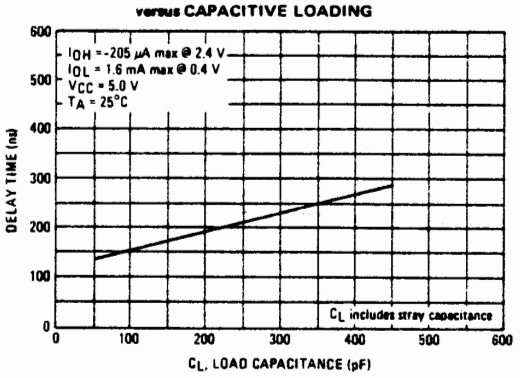
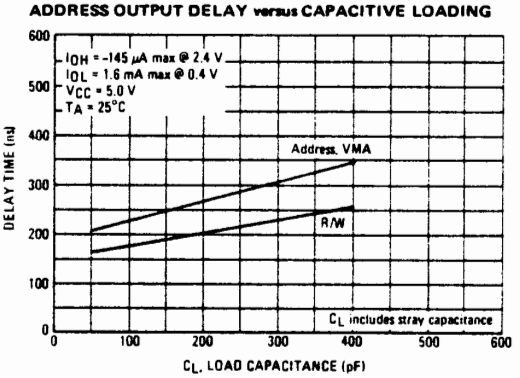
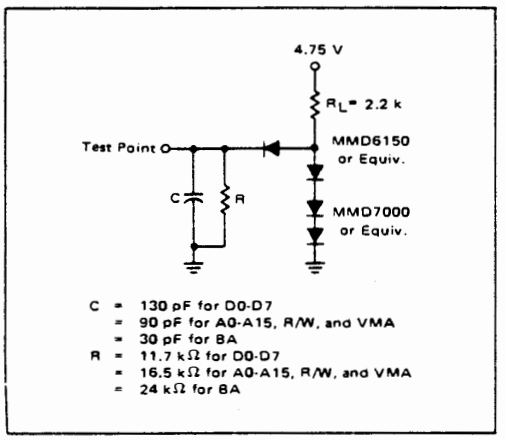


FIGURE 5 – TYPICAL READ/WRITE, VMA, AND ADDRESS OUTPUT DELAY versus CAPACITIVE LOADING



MC6800

FIGURE 6 – BUS TIMING TEST LOAD



C = 130 pF for D0-D7
= 90 pF for A0-A15, R/W, and VMA
= 30 pF for BA
R = 11.7 kΩ for D0-D7
= 16.5 kΩ for A0-A15, R/W, and VMA
= 24 kΩ for BA

TYPICAL POWER SUPPLY CURRENT

FIGURE 7 – VARIATIONS WITH FREQUENCY

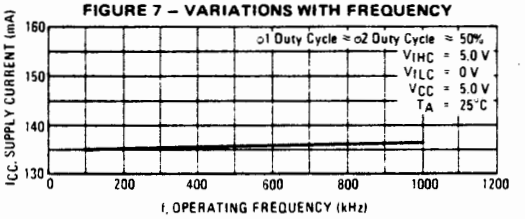
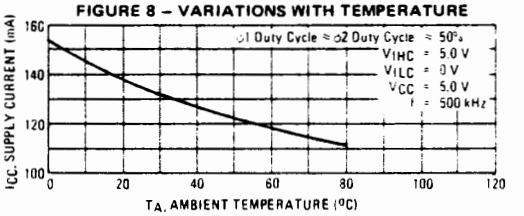
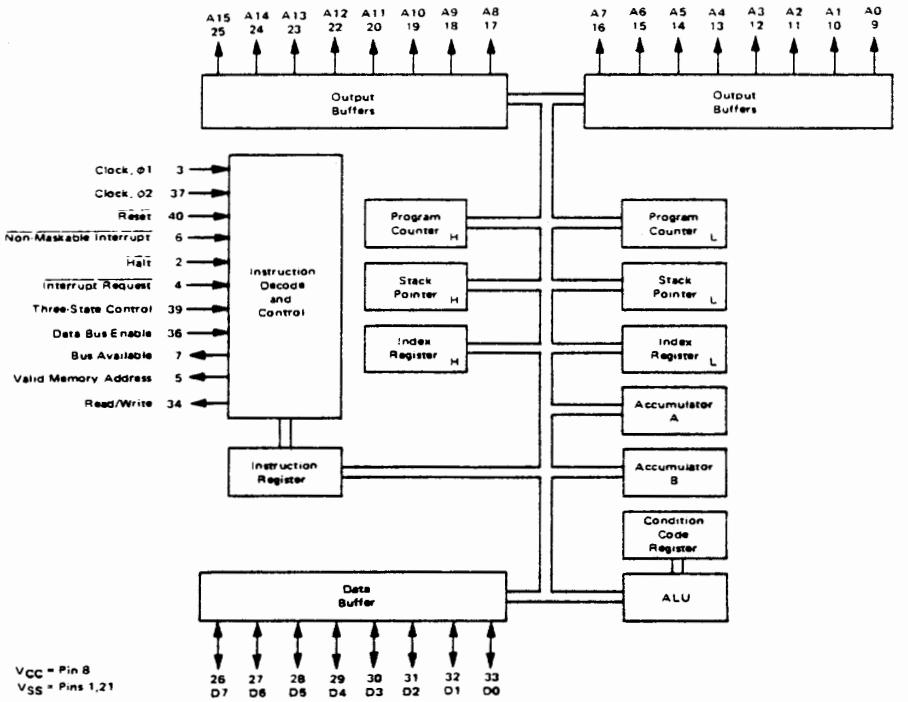


FIGURE 8 – VARIATIONS WITH TEMPERATURE



EXPANDED BLOCK DIAGRAM



MC6800

MPU SIGNAL DESCRIPTION

Proper operation of the MPU requires that certain control and timing signals be provided to accomplish specific functions and that other signal lines be monitored to determine the state of the processor.

Clocks Phase One and Phase Two (ϕ1, ϕ2) – Two pins are used for a two-phase non-overlapping clock that runs at the V_{CC} voltage level.

Address Bus (A0-A15) – Sixteen pins are used for the address bus. The outputs are three-state bus drivers capable of driving one standard TTL load and 130 pF. When the output is turned off, it is essentially an open circuit. This permits the MPU to be used in DMA applications.

Data Bus (D0-D7) – Eight pins are used for the data bus. It is bi-directional, transferring data to and from the memory and peripheral devices. It also has three-state output buffers capable of driving one standard TTL load and 130 pF.

$\overline{\text{Halt}}$ – When this input is in the low state, all activity in the machine will be halted. This input is level sensitive. In the halt mode, the machine will stop at the end of an instruction, Bus Available will be at a one level, Valid Memory Address will be at a zero, and all other three-state lines will be in the three-state mode.

Transition of the $\overline{\text{Halt}}$ line must not occur during the last 250 ns of phase one. To insure single instruction operation, the $\overline{\text{Halt}}$ line must go high for one Clock cycle.

Three-State Control (TSC) – This input causes all of the address lines and the Read/Write line to go into the off or high impedance state. This state will occur 700 ns after TSC = 2.0 V. The Valid Memory Address and Bus Available signals will be forced low. The data bus is not affected by TSC and has its own enable (Data Bus Enable). In DMA applications, the Three-State Control line should be brought high on the leading edge of the Phase One Clock. The ϕ1 clock must be held in the high state and the ϕ2 in the low state for this function to operate properly. The address bus will then be available for other devices to directly address memory. Since the MPU is a dynamic device, it can be held in this state for only 4.5 μs or destruction of data will occur in the MPU.

Read/Write (R/W) – This TTL compatible output signals the peripherals and memory devices whether the MPU is in a Read (high) or Write (low) state. The normal standby state of this signal is Read (high). Three-State Control going high will turn Read/Write to the off (high impedance) state. Also, when the processor is halted, it will be in the off state. This output is capable of driving one standard TTL load and 90 pF.

Valid Memory Address (VMA) – This output indicates to peripheral devices that there is a valid address on the address bus. In normal operation, this signal should be utilized for enabling peripheral interfaces such as the PIA and ACIA. This signal is not three-state. One standard TTL load and 90 pF may be directly driven by this active high signal.

Data Bus Enable (DBE) – This input is the three-state control signal for the MPU data bus and will enable the bus drivers when in the high state. This input is TTL compatible; however in normal operation, it would be driven by the phase two clock. During an MPU read cycle, the data bus drivers will be disabled internally. When it is desired that another device control the data bus such as in Direct Memory Access (DMA) applications, DBE should be held low.

Bus Available (BA) – The Bus Available signal will normally be in the low state; when activated, it will go to the high state indicating that the microprocessor has stopped and that the address bus is available. This will occur if the $\overline{\text{Halt}}$ line is in the low state or the processor is in the WAIT state as a result of the execution of a WAIT instruction. At such time, all three-state output drivers will go to their off state and other outputs to their normally inactive level. The processor is removed from the WAIT state by the occurrence of a maskable (mask bit I = 0) or nonmaskable interrupt. This output is capable of driving one standard TTL load and 30 pF.

Interrupt Request ($\overline{\text{IRQ}}$) – This level sensitive input requests that an interrupt sequence be generated within the machine. The processor will wait until it completes the current instruction that is being executed before it recognizes the request. At that time, if the interrupt mask bit in the Condition Code Register is not set, the machine will begin an interrupt sequence. The Index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. Next the MPU will respond to the interrupt request by setting the interrupt mask bit high so that no further interrupts may occur. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFF8 and FFF9. An address loaded at these locations causes the MPU to branch to an interrupt routine in memory.

The $\overline{\text{Halt}}$ line must be in the high state for interrupts to be serviced. Interrupts will be latched internally while $\overline{\text{Halt}}$ is low.

The $\overline{\text{IRQ}}$ has a high impedance pullup device internal to the chip; however a 3 kΩ external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

$\overline{\text{Reset}}$ – This input is used to reset and start the MPU from a power down condition, resulting from a power failure or an initial start-up of the processor. If a high level is detected on the input, this will signal the MPU to begin the restart sequence. This will start execution of a routine to initialize the processor from its reset condition. All the higher order address lines will be forced high. For the restart, the last two (FFFE, FFFF) locations in memory will be used to load the program that is addressed by the program counter. During the restart routine, the interrupt mask bit is set and must be reset before the MPU can be interrupted by $\overline{\text{IRQ}}$.

Figure 9 shows the initialization of the microprocessor after restart. $\overline{\text{Reset}}$ must be held low for at least eight clock periods after V_{CC} reaches 4.75 volts. If $\overline{\text{Reset}}$ goes high prior to the leading edge of $\phi 2$, on the next $\phi 1$ the first restart memory vector address (FFFE) will appear on the address lines. This location should contain the higher order eight bits to be stored into the program counter. Following, the next address FFFF should contain the lower order eight bits to be stored into the program counter.

Non-Maskable Interrupt ($\overline{\text{NMI}}$) – A low-going edge on this input requests that a non-mask-interrupt sequence be generated within the processor. As with the $\overline{\text{Interrupt Request}}$ signal, the processor will complete the current instruction that is being executed before it recognizes the $\overline{\text{NMI}}$ signal. The interrupt mask bit in the Condition Code Register has no effect on $\overline{\text{NMI}}$.

The Index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFFC and FFFD. An address loaded at these locations causes the MPU to branch to a non-maskable interrupt routine in memory.

$\overline{\text{NMI}}$ has a high impedance pullup resistor internal to the chip; however a 3 kΩ external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

Inputs $\overline{\text{IRQ}}$ and $\overline{\text{NMI}}$ are hardware interrupt lines that are sampled during $\phi 2$ and will start the interrupt routine on the $\phi 1$ following the completion of an instruction.

Figure 10 is a flow chart describing the major decision paths and interrupt vectors of the microprocessor. Table 1 gives the memory map for interrupt vectors.

FIGURE 9 – INITIALIZATION OF MPU AFTER RESTART

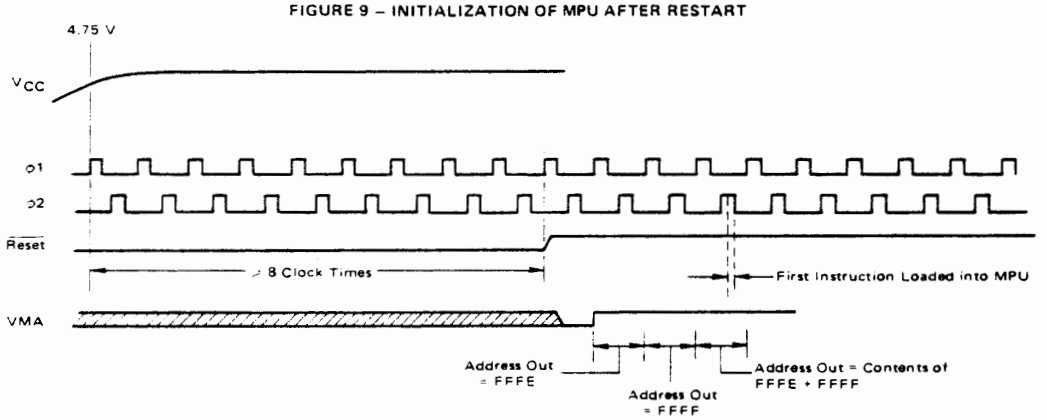
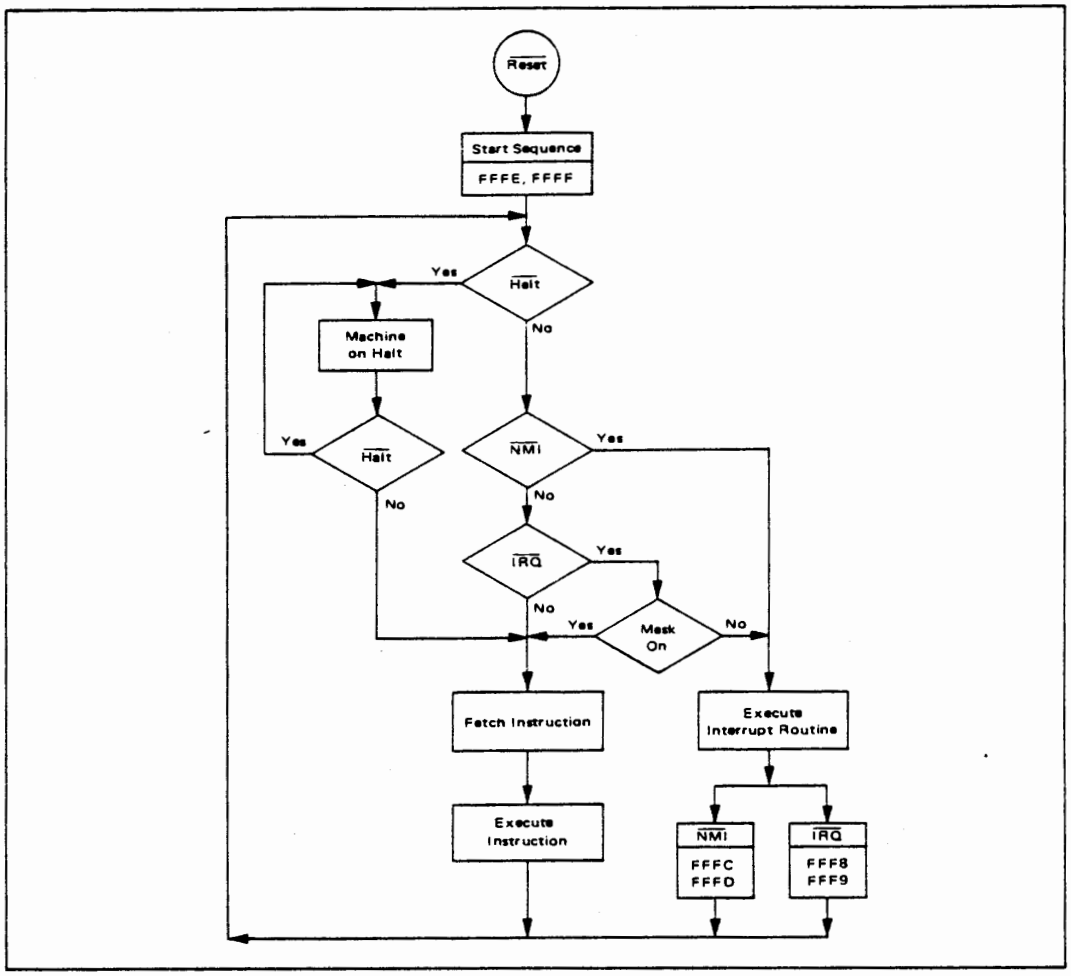


TABLE 1 – MEMORY MAP FOR INTERRUPT VECTORS

Vector MS	Vector LS	Description
FFFE	FFFF	Restart
FFFC	FFFD	Non-maskable Interrupt
FFFA	FFFB	Software Interrupt
FFF8	FFF9	Interrupt Request

FIGURE 10 – MPU FLOW CHART



MPU REGISTERS

The MPU has three 16-bit registers and three 8-bit registers available for use by the programmer (Figure 11).

Program Counter – The program counter is a two byte (16-bits) register that points to the current program address.

Stack Pointer – The stack pointer is a two byte register that contains the address of the next available location in an external push-down/pop-up stack. This stack is normally a random access Read/Write memory that may have any location (address) that is convenient. In those applications that require storage of information in the stack when power is lost, the stack must be non-volatile.

Index Register – The index register is a two byte register that is used to store data or a sixteen bit memory address for the Indexed mode of memory addressing.

Accumulators – The MPU contains two 8-bit accumulators that are used to hold operands and results from an arithmetic logic unit (ALU).

MC6800

FIGURE 11 – PROGRAMMING MODEL OF THE MICROPROCESSING UNIT

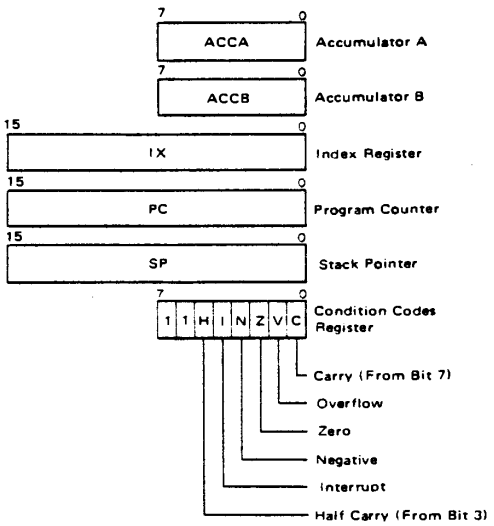
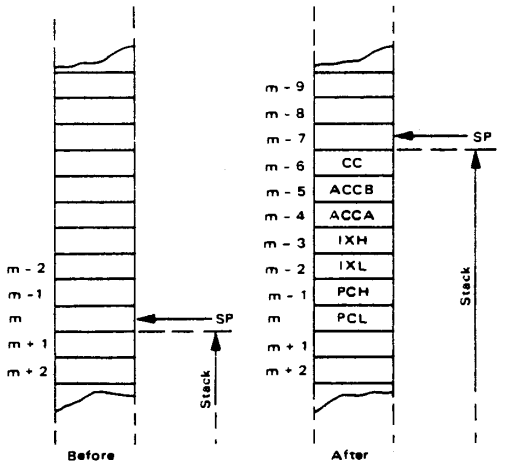


FIGURE 12 – SAVING THE STATUS OF THE MICROPROCESSOR IN THE STACK

SP = Stack Pointer
CC = Condition Codes (Also called the Processor Status Byte)
ACCB = Accumulator B
ACCA = Accumulator A
IXH = Index Register, Higher Order 8 Bits
IXL = Index Register, Lower Order 8 Bits
PCH = Program Counter, Higher Order 8 Bits
PCL = Program Counter, Lower Order 8 Bits



Condition Code Register – The condition code register indicates the results of an Arithmetic Logic Unit operation: Negative (N), Zero (Z), Overflow (V), Carry from bit 7 (C), and half carry from bit 3 (H). These bits of the Condition Code Register are used as testable conditions for the conditional branch instructions. Bit 4 is the interrupt mask bit (I). The unused bits of the Condition Code Register (b6 and b7) are ones.

Figure 12 shows the order of saving the microprocessor status within the stack.

MPU INSTRUCTION SET

The MC6800 has a set of 72 different instructions. Included are binary and decimal arithmetic, logical, shift, rotate, load, store, conditional or unconditional branch, interrupt and stack manipulation instructions (Tables 2 thru 6).

MPU ADDRESSING MODES

The MC6800 eight-bit microprocessing unit has seven address modes that can be used by a programmer, with the addressing mode a function of both the type of instruction and the coding within the instruction. A summary of the addressing modes for a particular instruction can be found in Table 7 along with the associated instruction execution time that is given in machine cycles. With a clock frequency of 1 MHz, these times would be microseconds.

Accumulator (ACCX) Addressing – In accumulator only addressing, either accumulator A or accumulator B is specified. These are one-byte instructions.

Immediate Addressing – In immediate addressing, the operand is contained in the second byte of the instruction except LDS and LDX which have the operand in the second and third bytes of the instruction. The MPU addresses this location when it fetches the immediate instruction for execution. These are two or three-byte instructions.

Direct Addressing – In direct addressing, the address of the operand is contained in the second byte of the instruction. Direct addressing allows the user to directly address the lowest 256 bytes in the machine i.e., locations zero through 255. Enhanced execution times are achieved by storing data in these locations. In most configurations, it should be a random access memory. These are two-byte instructions.

Extended Addressing – In extended addressing, the address contained in the second byte of the instruction is used as the higher eight-bits of the address of the operand. The third byte of the instruction is used as the lower eight-bits of the address for the operand. This is an absolute address in memory. These are three-byte instructions.

Indexed Addressing – In indexed addressing, the address contained in the second byte of the instruction is added to the index register's lowest eight bits in the MPU. The carry is then added to the higher order eight bits of the index register. This result is then used to address memory. The modified address is held in a temporary address register so there is no change to the index register. These are two-byte instructions.

Implied Addressing – In the implied addressing mode the instruction gives the address (i.e., stack pointer, index register, etc.). These are one-byte instructions.

Relative Addressing – In relative addressing, the address contained in the second byte of the instruction is added to the program counter's lowest eight bits plus two. The carry or borrow is then added to the high eight bits. This allows the user to address data within a range of -125 to +129 bytes of the present instruction. These are two-byte instructions.

TABLE 2 – MICROPROCESSOR INSTRUCTION SET – ALPHABETIC SEQUENCE

ABA	Add Accumulators	CLR	Clear	PUL	Pull Data
ADC	Add with Carry	CLV	Clear Overflow	ROL	Rotate Left
ADD	Add	CMP	Compare	ROR	Rotate Right
AND	Logical And	COM	Complement	RTI	Return from Interrupt
ASL	Arithmetic Shift Left	CPX	Compare Index Register	RTS	Return from Subroutine
ASR	Arithmetic Shift Right	DAA	Decimal Adjust	SBA	Subtract Accumulators
BCC	Branch if Carry Clear	DEC	Decrement	SBC	Subtract with Carry
BCS	Branch if Carry Set	DES	Decrement Stack Pointer	SEC	Set Carry
BEQ	Branch if Equal to Zero	DEX	Decrement Index Register	SEI	Set Interrupt Mask
BGE	Branch if Greater or Equal Zero	EOR	Exclusive OR	SEV	Set Overflow
BGT	Branch if Greater than Zero	INC	Increment	STA	Store Accumulator
BHI	Branch if Higher	INS	Increment Stack Pointer	STS	Store Stack Register
BIT	Bit Test	INX	Increment Index Register	STX	Store Index Register
BLE	Branch if Less or Equal	JMP	Jump	SUB	Subtract
BLS	Branch if Lower or Same	JSR	Jump to Subroutine	SWI	Software Interrupt
BLT	Branch if Less than Zero	LDA	Load Accumulator	TAB	Transfer Accumulators
BMI	Branch if Minus	LDS	Load Stack Pointer	TAP	Transfer Accumulators to Condition Code Reg.
BNE	Branch if Not Equal to Zero	LDX	Load Index Register	TBA	Transfer Accumulators
BPL	Branch if Plus	LSR	Logical Shift Right	TPA	Transfer Condition Code Reg. to Accumulator
BRA	Branch Always	NEG	Negate	TST	Test
BSR	Branch to Subroutine	NOP	No Operation	TSX	Transfer Stack Pointer to Index Register
BVC	Branch if Overflow Clear	ORA	Inclusive OR Accumulator	TXS	Transfer Index Register to Stack Pointer
BVS	Branch if Overflow Set	PSH	Push Data	WAI	Wait for Interrupt
CBA	Compare Accumulators				
CLC	Clear Carry				
CLI	Clear Interrupt Mask				

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TABLE 3 – ACCUMULATOR AND MEMORY INSTRUCTIONS

OPERATIONS	MNEMONIC	IMMED OP	IMMED ~	IMMED #	DIRECT OP	DIRECT ~	DIRECT #	INDEX OP	INDEX ~	INDEX #	EXTND OP	EXTND ~	EXTND #	IMPLIED OP	IMPLIED ~	IMPLIED #	BOOLEAN/ARITHMETIC OPERATION (All register labels refer to contents)	5 H	4 I	3 N	2 Z	1 V	0 C
Add	ADDA	3B	2	2	9B	3	2	AB	5	2	BB	4	3				A + M → A	↕	•	↕	↕	↕	↕
	ADDB	CB	2	2	DB	3	2	EB	5	2	FB	4	3				B + M → B	↕	•	↕	↕	↕	↕
Add Acmltrs	ABA													1B	2	1	A + B → A	↕	•	↕	↕	↕	↕
Add with Carry	ADCA	89	2	2	99	3	2	A9	5	2	B9	4	3				A + M + C → A	↕	•	↕	↕	↕	↕
	ADCB	C9	2	2	D9	3	2	E9	5	2	F9	4	3				B + M + C → B	↕	•	↕	↕	↕	↕
And	ANDA	84	2	2	94	3	2	A4	5	2	B4	4	3				A · M → A	•	•	↕	↕	R	•
	ANDB	C4	2	2	D4	3	2	E4	5	2	F4	4	3				B · M → B	•	•	↕	↕	R	•
Bit Test	BITA	85	2	2	95	3	2	A5	5	2	B5	4	3				A · M	•	•	↕	↕	R	•
	BITB	C5	2	2	D5	3	2	E5	5	2	F5	4	3				B · M	•	•	↕	↕	R	•
Clear	CLR							6F	7	2	7F	6	3				00 → M	•	•	R	S	R	R
	CLRA													4F	2	1	00 → A	•	•	R	S	R	R
	CLRB													5F	2	1	00 → B	•	•	R	S	R	R
Compare	CMPA	81	2	2	91	3	2	A1	5	2	B1	4	3				A − M	•	•	↕	↕	↕	↕
	CMPB	C1	2	2	D1	3	2	E1	5	2	F1	4	3				B − M	•	•	↕	↕	↕	↕
Compare Acmltrs	CBA													11	2	1	A − B	•	•	↕	↕	↕	↕
Complement, 1's	COM							63	7	2	73	6	3				M̄ → M	•	•	↕	↕	R	S
	COMA													43	2	1	Ā → A	•	•	↕	↕	R	S
	COMB													53	2	1	B̄ → B	•	•	↕	↕	R	S
Complement, 2's (Negate)	NEG							60	7	2	70	6	3				00 − M → M	•	•	↕	↕	↕	↕ ②
	NEGA													40	2	1	00 − A → A	•	•	↕	↕	↕	↕ ②
	NEGB													50	2	1	00 − B → B	•	•	↕	↕	↕	↕ ②
Decimal Adjust, A	DAA													19	2	1	Converts Binary Add of BCD Characters into BCD Format	•	•	↕	↕	↕	↕ ①
Decrement	DEC							6A	7	2	7A	6	3				M − 1 → M	•	•	↕	↕	•	•
	DECA													4A	2	1	A − 1 → A	•	•	↕	↕	•	•
	DECB													5A	2	1	B − 1 → B	•	•	↕	↕	•	•
Exclusive OR	EORA	88	2	2	98	3	2	A8	5	2	B8	4	3				A⊕M → A	•	•	↕	↕	R	•
	EORB	C8	2	2	D8	3	2	E8	5	2	F8	4	3				B⊕M → B	•	•	↕	↕	R	•
Increment	INC							6C	7	2	7C	6	3				M + 1 → M	•	•	↕	↕	↕	•
	INCA													4C	2	1	A + 1 → A	•	•	↕	↕	↕	•
	INCB													5C	2	1	B + 1 → B	•	•	↕	↕	↕	•
Load Acmltr	LDAA	86	2	2	96	3	2	A6	5	2	B6	4	3				M → A	•	•	↕	↕	R	•
	LDAB	C6	2	2	D6	3	2	E6	5	2	F6	4	3				M → B	•	•	↕	↕	R	•
Or, Inclusive	ORAA	8A	2	2	9A	3	2	AA	5	2	BA	4	3				A + M → A	•	•	↕	↕	R	•
	ORAB	CA	2	2	DA	3	2	EA	5	2	FA	4	3				B + M → B	•	•	↕	↕	R	•
Push Data	PSHA													36	4	1	A → Msp, SP − 1 → SP	•	•	•	•	•	•
	PSHB													37	4	1	B → Msp, SP − 1 → SP	•	•	•	•	•	•
Pull Data	PULA													32	4	1	SP + 1 → SP, Msp → A	•	•	•	•	•	•
	PULB													33	4	1	SP + 1 → SP, Msp → B	•	•	•	•	•	•
Rotate Left	ROL							69	7	2	79	6	3				M	•	•	↕	↕	↕	↕
	ROLA													49	2	1	A	•	•	↕	↕	↕	↕
	ROLB													59	2	1	B	•	•	↕	↕	↕	↕
Rotate Right	ROR							66	7	2	76	6	3				M	•	•	↕	↕	↕	↕
	RORA													46	2	1	A	•	•	↕	↕	↕	↕
	RORB													56	2	1	B	•	•	↕	↕	↕	↕
Shift Left, Arithmetic	ASL							68	7	2	78	6	3				M	•	•	↕	↕	↕	↕
	ASLA													48	2	1	A	•	•	↕	↕	↕	↕
	ASLB													58	2	1	B	•	•	↕	↕	↕	↕
Shift Right, Arithmetic	ASR							67	7	2	77	6	3				M	•	•	↕	↕	↕	↕
	ASRA													47	2	1	A	•	•	↕	↕	↕	↕
	ASRB													57	2	1	B	•	•	↕	↕	↕	↕
Shift Right, Logic	LSR							64	7	2	74	6	3				M	•	•	R	↕	↕	↕
	LSRA													44	2	1	A	•	•	R	↕	↕	↕
	LSRB													54	2	1	B	•	•	R	↕	↕	↕
Store Acmltr	STAA				97	4	2	A7	6	2	B7	5	3				A → M	•	•	↕	↕	R	•
	STAB				D7	4	2	E7	6	2	F7	5	3				B → M	•	•	↕	↕	R	•
Subtract	SUBA	80	2	2	90	3	2	A0	5	2	B0	4	3				A − M → A	•	•	↕	↕	↕	↕
	SUBB	C0	2	2	D0	3	2	E0	5	2	F0	4	3				B − M → B	•	•	↕	↕	↕	↕
Subtract Acmltrs	SBA													10	2	1	A − B → A	•	•	↕	↕	↕	↕
Subtract with Carry	SBCA	82	2	2	92	3	2	A2	5	2	B2	4	3				A − M − C → A	•	•	↕	↕	↕	↕
	SBCB	C2	2	2	D2	3	2	E2	5	2	F2	4	3				B − M − C → B	•	•	↕	↕	↕	↕
Transfer Acmltrs	TAB													16	2	1	A → B	•	•	↕	↕	R	•
	TBA													17	2	1	B → A	•	•	↕	↕	R	•
Test, Zero or Minus	TST							6D	7	2	7D	6	3				M − 00	•	•	↕	↕	R	R
	TSTA													4D	2	1	A − 00	•	•	↕	↕	R	R
	TSTB													5D	2	1	B − 00	•	•	↕	↕	R	R
																		H	I	N	Z	V	C

ADDRESSING MODES

BOOLEAN/ARITHMETIC OPERATION

CONDITION CODE REG.

LEGEND:

OP Operation Code (Hexadecimal)
~ Number of MPU Cycles
# Number of Program Bytes
+ Arithmetic Plus
− Arithmetic Minus
· Boolean AND
Msp Contents of memory location pointed to be Stack Pointer
+ Boolean Inclusive OR
⊕ Boolean Exclusive OR
M̄ Complement of M
→ Transfer into
0 Bit = Zero
00 Byte = Zero

Note – Accumulator addressing mode instructions are included in the column for IMPLIED addressing

CONDITION CODE SYMBOLS:

H Half-carry from bit 3
I Interrupt mask
N Negative (sign) bit
Z Zero (byte)
V Overflow, 2's complement
C Carry from bit 7
R Reset Always
S Set Always
↕ Test and set if true, cleared otherwise
• Not Affected

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TABLE 4 – INDEX REGISTER AND STACK MANIPULATION INSTRUCTIONS

		IMMED			DIRECT			INDEX			EXTND			IMPLIED				COND. CODE REG.					
																		5	4	3	2	1	0
POINTER OPERATIONS	MNEMONIC	OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	BOOLEAN/ARITHMETIC OPERATION	H	I	N	Z	V	C
Compare Index Reg	CPX	8C	3	3	9C	4	2	AC	6	2	BC	5	3				$X_H - M, X_L - (M+1)$	•	•	⑦	↕	⑧	•
Decrement Index Reg	DEX													09	4	1	$X - 1 \rightarrow X$	•	•	•	↕	•	•
Decrement Stack Pntr	DES													34	4	1	$SP - 1 \rightarrow SP$	•	•	•	•	•	•
Increment Index Reg	INX													08	4	1	$X + 1 \rightarrow X$	•	•	•	↕	•	•
Increment Stack Pntr	INS													31	4	1	$SP + 1 \rightarrow SP$	•	•	•	•	•	•
Load Index Reg	LDX	CE	3	3	DE	4	2	EE	6	2	FE	5	3				$M \rightarrow X_H, (M+1) \rightarrow X_L$	•	•	③	↕	R	•
Load Stack Pntr	LDS	8E	3	3	9E	4	2	AE	6	2	BE	5	3				$M \rightarrow SP_H, (M+1) \rightarrow SP_L$	•	•	⑨	↕	R	•
Store Index Reg	STX				DF	5	2	EF	7	2	FF	6	3				$X_H \rightarrow M, X_L \rightarrow (M+1)$	•	•	⑨	↕	R	•
Store Stack Pntr	STS				9F	5	2	AF	7	2	BF	6	3				$SP_H \rightarrow M, SP_L \rightarrow (M+1)$	•	•	⑨	↕	R	•
Indx Reg → Stack Pntr	TXS													35	4	1	$X - 1 \rightarrow SP$	•	•	•	•	•	•
Stack Pntr → Indx Reg	TSX													30	4	1	$SP + 1 \rightarrow X$	•	•	•	•	•	•

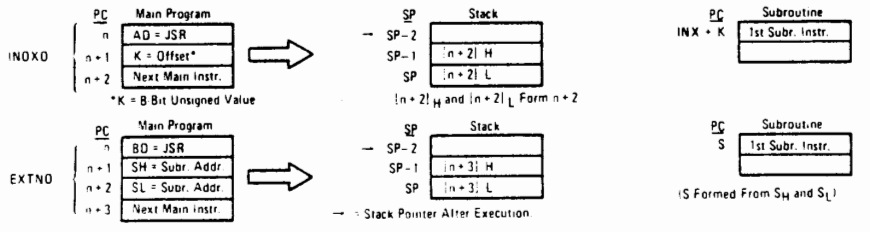
TABLE 5 – JUMP AND BRANCH INSTRUCTIONS

		RELATIVE			INDEX			EXTND			IMPLIED				COND. CODE REG.						
															5	4	3	2	1	0	
OPERATIONS	MNEMONIC	OP	~	#	OP	~	#	OP	~	#	OP	~	#	BRANCH TEST	H	I	N	Z	V	C	
Branch Always	BRA	20	4	2										None	•	•	•	•	•	•	
Branch If Carry Clear	BCC	24	4	2										C = 0	•	•	•	•	•	•	
Branch If Carry Set	BCS	25	4	2										C = 1	•	•	•	•	•	•	
Branch If = Zero	BEQ	27	4	2										Z = 1	•	•	•	•	•	•	
Branch If ≥ Zero	BGE	2C	4	2										$N \oplus V = 0$	•	•	•	•	•	•	
Branch If > Zero	BGT	2E	4	2										$Z + (N \oplus V) = 0$	•	•	•	•	•	•	
Branch If Higher	BHI	22	4	2										$C + Z = 0$	•	•	•	•	•	•	
Branch If ≤ Zero	BLE	2F	4	2										$Z + (N \oplus V) = 1$	•	•	•	•	•	•	
Branch If Lower Or Same	BLS	23	4	2										$C + Z = 1$	•	•	•	•	•	•	
Branch If < Zero	BLT	2D	4	2										$N \oplus V = 1$	•	•	•	•	•	•	
Branch If Minus	BMI	2B	4	2										N = 1	•	•	•	•	•	•	
Branch If Not Equal Zero	BNE	26	4	2										Z = 0	•	•	•	•	•	•	
Branch If Overflow Clear	BVC	28	4	2										V = 0	•	•	•	•	•	•	
Branch If Overflow Set	BVS	29	4	2										V = 1	•	•	•	•	•	•	
Branch If Plus	BPL	2A	4	2										N = 0	•	•	•	•	•	•	
Branch To Subroutine	BSR	8D	8	2											•	•	•	•	•	•	
Jump	JMP				6E	4	2	7E	3	3				See Special Operations	•	•	•	•	•	•	
Jump To Subroutine	JSR				AD	8	2	BD	9	3					•	•	•	•	•	•	
No Operation	NOP										01	2	1	Advances Prog. Cntr. Only	•	•	•	•	•	•	
Return From Interrupt	RTI										3B	10	1		———			⑩		———	
Return From Subroutine	RTS										39	5	1		•	•	•	•	•	•	
Software Interrupt	SWI										3F	12	1	See Special Operations	•	•	•	•	•	•	
Wait for Interrupt*	WAI										3E	9	1		•	⑪	•	•	•	•	

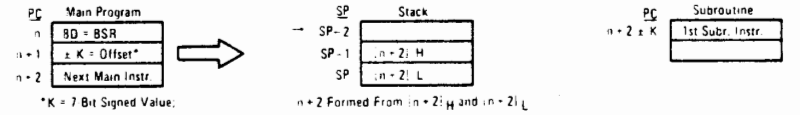
*WAI puts Address Bus, R/W, and Data Bus in the three-state mode while VMA is held low.

SPECIAL OPERATIONS

JSR, JUMP TO SUBROUTINE:

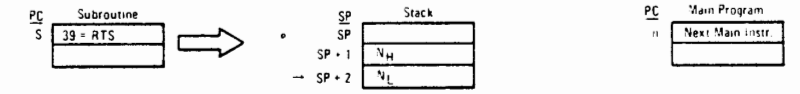


BSR, BRANCH TO SUBROUTINE:



JMP, JUMP:

RTS, RETURN FROM SUBROUTINE:



RTI, RETURN FROM INTERRUPT:

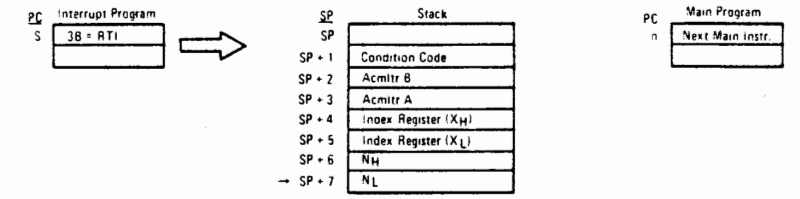


TABLE 6 – CONDITION CODE REGISTER MANIPULATION INSTRUCTIONS

OPERATIONS	MNEMONIC	IMPLIED OP	~	=	BOOLEAN OPERATION	COND. CODE REG. 5 H	4 I	3 N	2 Z	1 V	0 C
Clear Carry	CLC	0C	2	1	0 → C	•	•	•	•	•	R
Clear Interrupt Mask	CLI	0E	2	1	0 → I	•	R	•	•	•	•
Clear Overflow	CLV	0A	2	1	0 → V	•	•	•	•	R	•
Set Carry	SEC	0D	2	1	1 → C	•	•	•	•	•	S
Set Interrupt Mask	SEI	0F	2	1	1 → I	•	S	•	•	•	•
Set Overflow	SEV	0B	2	1	1 → V	•	•	•	•	S	•
Acmltr A → CCR	TAP	06	2	1	A → CCR	——— (12) ———					
CCR → Acmltr A	TPA	07	2	1	CCR → A	•	•	•	•	•	•

CONDITION CODE REGISTER NOTES: (Bit set if test is true and cleared otherwise)

1 (Bit V) Test: Result = 10000000?
2 (Bit C) Test: Result = 00000000?
3 (Bit C) Test: Decimal value of most significant BCD Character greater than nine? (Not cleared if previously set.)
4 (Bit V) Test: Operand = 10000000 prior to execution?
5 (Bit V) Test: Operand = 01111111 prior to execution?
6 (Bit V) Test: Set equal to result of N⊕C after shift has occurred.
7 (Bit N) Test: Sign bit of most significant (MS) byte = 1?
8 (Bit V) Test: 2's complement overflow from subtraction of MS bytes?
9 (Bit N) Test: Result less than zero? (Bit 15 = 1)
10 (All) Load Condition Code Register from Stack. (See Special Operations)
11 (Bit I) Set when interrupt occurs. If previously set, a Non-Maskable Interrupt is required to exit the wait state.
12 (All) Set according to the contents of Accumulator A.

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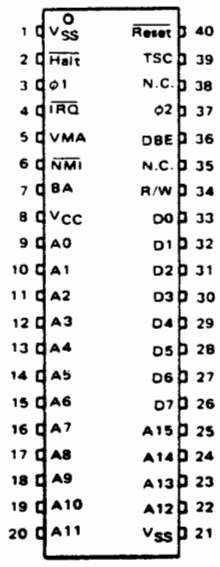
TABLE 7 – INSTRUCTION ADDRESSING MODES AND ASSOCIATED EXECUTION TIMES
(Times in Machine Cycles)

	(Dual Operand)	ACCX	Immediate	Direct	Extended	Indexed	Implied	Relative
ABA							2	
ADC	x		2	3	4	5		
ADD	x		2	3	4	5		
AND	x		2	3	4	5		
ASL		2			6	7		
ASR		2			6	7		
BCC								4
BCS								4
BEA								4
BGE								4
BGT								4
BHI								4
BIT	x		2	3	4	5		
BLE								4
BLS								4
BLT								4
BMI								4
BNE								4
BPL								4
BRA								4
BSR								8
BVC								4
BVS								4
CBA							2	
CLC							2	
CLI							2	
CLR		2			6	7		
CLV							2	
CMP	x		2	3	4	5		
COM		2			6	7		
CPX			3	4	5	6		
DAA							2	
DEC		2			6	7		
DES							4	
DEX							4	
EOR	x		2	3	4	5		

	(Dual Operand)	ACCX	Immediate	Direct	Extended	Indexed	Implied
INC		2			6	7	
INS							4
INX							4
JMP						3	4
JSR						9	8
LDA	x		2	3	4	5	
LDS			3	4	5	6	
LDX			3	4	5	6	
LSR		2			6	7	
NEG		2			6	7	
NOP							2
ORA	x		2	3	4	5	
PSH							4
PUL							4
ROL		2			6	7	
ROR		2			6	7	
RTI							10
RTS							5
SBA							2
SBC	x		2	3	4	5	
SEC							2
SEI							2
SEV							2
STA	x			4	5	6	
STS				5	6	7	
STX				5	6	7	
SUB	x		2	3	4	5	
SWI							12
TAB							2
TAP							2
TBA							2
TPA							2
TST		2			6	7	
TSX							4
TSX							4
WAI							9

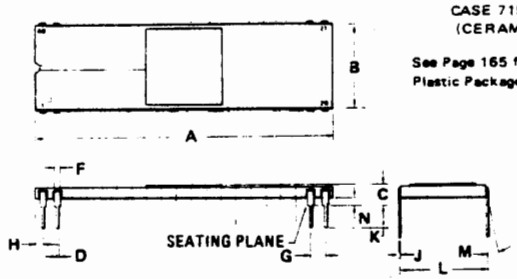
NOTE Interrupt time is 12 cycles from the end of the instruction being executed, except following a WAI instruction. Then it is 4 cycles

PIN ASSIGNMENT



PACKAGE DIMENSIONS
CASE 715-02
(CERAMIC)

See Page 165 for Plastic Package dimensions.



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	50.29	51.31	1.980	2.020
B	14.86	15.62	0.585	0.615
C	2.54	4.19	0.100	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.40	0.030	0.055
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.33	0.008	0.013
K	2.54	4.19	0.100	0.165
L	14.60	15.37	0.575	0.605
M	-	10°	-	10°
N	0.51	1.52	0.020	0.060

NOTE:
1. LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIA (AT SEATING PLANE), AT MAX. MAT'L CONDITION.

SUMMARY OF CYCLE BY CYCLE OPERATION

Table 8 provides a detailed description of the information present on the Address Bus, Data Bus, Valid Memory Address line (VMA), and the Read/Write line (R/W) during each cycle for each instruction.

This information is useful in comparing actual with expected results during debug of both software and hardware as the control program is executed. The information is categorized in groups according to Addressing Mode and Number of Cycles per instruction. (In general, instructions with the same Addressing Mode and Number of Cycles execute in the same manner; exceptions are indicated in the table.)

TABLE 8 – OPERATION SUMMARY

Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
IMMEDIATE						
ADC EOR ADD LDA AND ORA BIT SBC CMP SUB	2	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Operand Data
CPX LDS LDX	3	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Operand Data (High Order Byte)
		3	1	Op Code Address + 2	1	Operand Data (Low Order Byte)
DIRECT						
ADC EOR ADD LDA AND ORA BIT SBC CMP SUB	3	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Operand
		3	1	Address of Operand	1	Operand Data
CPX LDS LDX	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Operand
		3	1	Address of Operand	1	Operand Data (High Order Byte)
		4	1	Operand Address + 1	1	Operand Data (Low Order Byte)
STA	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Destination Address
		3	0	Destination Address	1	Irrelevant Data (Note 1)
		4	1	Destination Address	0	Data from Accumulator
STS STX	5	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Operand
		3	0	Address of Operand	1	Irrelevant Data (Note 1)
		4	1	Address of Operand	0	Register Data (High Order Byte)
		5	1	Address of Operand + 1	0	Register Data (Low Order Byte)
INDEXED						
JMP	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
ADC EOR ADD LDA AND ORA BIT SBC CMP SUB	5	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	1	Index Register Plus Offset	1	Operand Data
CPX LDS LDX	6	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	1	Index Register Plus Offset	1	Operand Data (High Order Byte)
		6	1	Index Register Plus Offset + 1	1	Operand Data (Low Order Byte)

MC6800

TABLE 8 – OPERATION SUMMARY (Continued)

Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
INDEXED (Continued)						
STA	6	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)
		6	1	Index Register Plus Offset	0	Operand Data
ASL LSR ASR NEG CLR ROL COM ROR DEC TST INC	7	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	1	Index Register Plus Offset	1	Current Operand Data
		6	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)
		7	1/0 (Note 3)	Index Register Plus Offset	0	New Operand Data (Note 3)
STS STX	7	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)
		6	1	Index Register Plus Offset	0	Operand Data (High Order Byte)
		7	1	Index Register Plus Offset + 1	0	Operand Data (Low Order Byte)
JSR	8	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer	0	Return Address (Low Order Byte)
		5	1	Stack Pointer – 1	0	Return Address (High Order Byte)
		6	0	Stack Pointer – 2	1	Irrelevant Data (Note 1)
		7	0	Index Register	1	Irrelevant Data (Note 1)
		8	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
EXTENDED						
JMP	3	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Jump Address (High Order Byte)
		3	1	Op Code Address + 2	1	Jump Address (Low Order Byte)
ADC EOR ADD LDA AND ORA BIT SBC CMP SUB	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)
		3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)
		4	1	Address of Operand	1	Operand Data
CPX LDS LDX	5	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)
		3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)
		4	1	Address of Operand	1	Operand Data (High Order Byte)
		5	1	Address of Operand + 1	1	Operand Data (Low Order Byte)
STA A STA B	5	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Destination Address (High Order Byte)
		3	1	Op Code Address + 2	1	Destination Address (Low Order Byte)
		4	0	Operand Destination Address	1	Irrelevant Data (Note 1)
		5	1	Operand Destination Address	0	Data from Accumulator
ASL LSR ASR NEG CLR ROL COM ROR DEC TST INC	6	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)
		3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)
		4	1	Address of Operand	1	Current Operand Data
		5	0	Address of Operand	1	Irrelevant Data (Note 1)
		6	1/0 (Note 3)	Address of Operand	0	New Operand Data (Note 3)

MC6800

TABLE 8 – OPERATION SUMMARY (Continued)

Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
EXTENDED (Continued)						
STS STX	6	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)
		3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)
		4	0	Address of Operand	1	Irrelevant Data (Note 1)
		5	1	Address of Operand	0	Operand Data (High Order Byte)
		6	1	Address of Operand + 1	0	Operand Data (Low Order Byte)
JSR	9	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Subroutine (High Order Byte)
		3	1	Op Code Address + 2	1	Address of Subroutine (Low Order Byte)
		4	1	Subroutine Starting Address	1	Op Code of Next Instruction
		5	1	Stack Pointer	0	Return Address (Low Order Byte)
		6	1	Stack Pointer – 1	0	Return Address (High Order Byte)
		7	0	Stack Pointer – 2	1	Irrelevant Data (Note 1)
		8	0	Op Code Address + 2	1	Irrelevant Data (Note 1)
		9	1	Op Code Address + 2	1	Address of Subroutine (Low Order Byte)
INHERENT						
ABA DAA SEC ASL DEC SEI ASR INC SEV CBA LSR TAB CLC NEG TAP CLI NOP TBA CLR ROL TPA CLV ROR TST COM SBA	2	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
DES DEX INS INX	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	0	Previous Register Contents	1	Irrelevant Data (Note 1)
		4	0	New Register Contents	1	Irrelevant Data (Note 1)
PSH	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	1	Stack Pointer	0	Accumulator Data
		4	0	Stack Pointer – 1	1	Accumulator Data
PUL	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1	Operand Data from Stack
TSX	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	0	New Index Register	1	Irrelevant Data (Note 1)
TXS	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	0	Index Register	1	Irrelevant Data
		4	0	New Stack Pointer	1	Irrelevant Data
RTS	5	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 2)
		3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1	Address of Next Instruction (High Order Byte)
		5	1	Stack Pointer + 2	1	Address of Next Instruction (Low Order Byte)

MC6800

TABLE 8 – OPERATION SUMMARY (Continued)

Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
INHERENT (Continued)						
WAI	9	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	1	Stack Pointer	0	Return Address (Low Order Byte)
		4	1	Stack Pointer – 1	0	Return Address (High Order Byte)
		5	1	Stack Pointer – 2	0	Index Register (Low Order Byte)
		6	1	Stack Pointer – 3	0	Index Register (High Order Byte)
		7	1	Stack Pointer – 4	0	Contents of Accumulator A
		8	1	Stack Pointer – 5	0	Contents of Accumulator B
		9	1	Stack Pointer – 6 (Note 4)	1	Contents of Cond. Code Register
RTI	10	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 2)
		3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1	Contents of Cond. Code Register from Stack
		5	1	Stack Pointer + 2	1	Contents of Accumulator B from Stack
		6	1	Stack Pointer + 3	1	Contents of Accumulator A from Stack
		7	1	Stack Pointer + 4	1	Index Register from Stack (High Order Byte)
		8	1	Stack Pointer + 5	1	Index Register from Stack (Low Order Byte)
		9	1	Stack Pointer + 6	1	Next Instruction Address from Stack (High Order Byte)
		10	1	Stack Pointer + 7	1	Next Instruction Address from Stack (Low Order Byte)
SWI	12	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 1)
		3	1	Stack Pointer	0	Return Address (Low Order Byte)
		4	1	Stack Pointer – 1	0	Return Address (High Order Byte)
		5	1	Stack Pointer – 2	0	Index Register (Low Order Byte)
		6	1	Stack Pointer – 3	0	Index Register (High Order Byte)
		7	1	Stack Pointer – 4	0	Contents of Accumulator A
		8	1	Stack Pointer – 5	0	Contents of Accumulator B
		9	1	Stack Pointer – 6	0	Contents of Cond. Code Register
		10	0	Stack Pointer – 7	1	Irrelevant Data (Note 1)
		11	1	Vector Address FFFA (Hex)	1	Address of Subroutine (High Order Byte)
		12	1	Vector Address FFFB (Hex)	1	Address of Subroutine (Low Order Byte)
RELATIVE						
BCC BHI BNE BCS BLE BPL BEQ BLS BRA BGE BLT BVC BGT BMI BVS	4	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Branch Offset
		3	0	Op Code Address + 2	1	Irrelevant Data (Note 1)
		4	0	Branch Address	1	Irrelevant Data (Note 1)
BSR	8	1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Branch Offset
		3	0	Return Address of Main Program	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer	0	Return Address (Low Order Byte)
		5	1	Stack Pointer – 1	0	Return Address (High Order Byte)
		6	0	Stack Pointer – 2	1	Irrelevant Data (Note 1)
		7	0	Return Address of Main Program	1	Irrelevant Data (Note 1)
		8	0	Subroutine Address	1	Irrelevant Data (Note 1)

Note 1. If device which is addressed during this cycle uses VMA, then the Data Bus will go to the high impedance three-state condition. Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus.
Note 2. Data is ignored by the MPU.
Note 3. For TST, VMA = 0 and Operand data does not change.
Note 4. While the MPU is waiting for the interrupt, Bus Available will go high indicating the following states of the control lines: VMA is low; Address Bus, R/W, and Data Bus are all in the high impedance state.

MOTOROLA Semiconductors
BOX 20912 • PHOENIX, ARIZONA 85036

MC6820
(0 to 70°C; L or P Suffix)

MC6820C
(-40 to 85°C; L Suffix only)

PERIPHERAL INTERFACE ADAPTER (PIA)

The MC6820 Peripheral Interface Adapter provides the universal means of interfacing peripheral equipment to the MC6800 Microprocessing Unit (MPU). This device is capable of interfacing the MPU to peripherals through two 8-bit bidirectional peripheral data buses and four control lines. No external logic is required for interfacing to most peripheral devices.

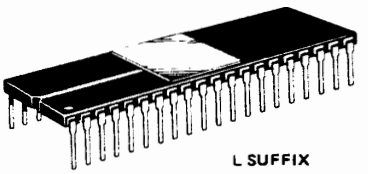
The functional configuration of the PIA is programmed by the MPU during system initialization. Each of the peripheral data lines can be programmed to act as an input or output, and each of the four control/interrupt lines may be programmed for one of several control modes. This allows a high degree of flexibility in the over-all operation of the interface.

- 8-Bit Bidirectional Data Bus for Communication with the MPU
- Two Bidirectional 8-Bit Buses for Interface to Peripherals
- Two Programmable Control Registers
- Two Programmable Data Direction Registers
- Four Individually-Controlled Interrupt Input Lines; Two Usable as Peripheral Control Outputs
- Handshake Control Logic for Input and Output Peripheral Operation
- High-Impedance 3-State and Direct Transistor Drive Peripheral Lines
- Program Controlled Interrupt and Interrupt Disable Capability
- CMOS Drive Capability on Side A Peripheral Lines

MOS

(N-CHANNEL, SILICON-GATE)

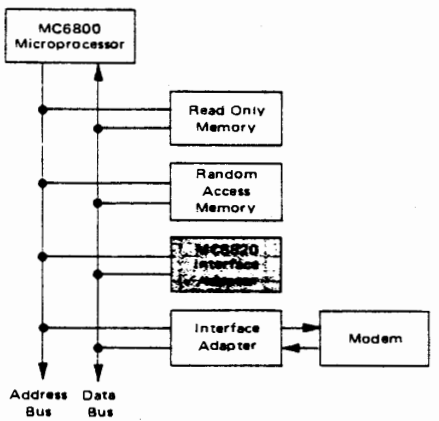
PERIPHERAL INTERFACE ADAPTER



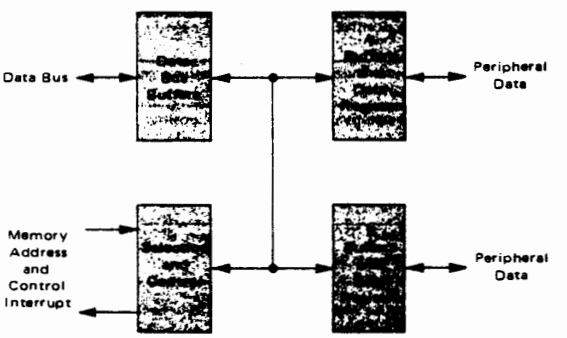
L SUFFIX
CERAMIC PACKAGE
CASE 715

NOT SHOWN: P SUFFIX
PLASTIC PACKAGE
CASE 711

M6800 MICROCOMPUTER FAMILY BLOCK DIAGRAM



MC6820 PERIPHERAL INTERFACE ADAPTER BLOCK DIAGRAM



MC6820

ELECTRICAL CHARACTERISTICS (V_{CC} = 5.0 V ±5%, V_{SS} = 0, T_A = 0 to 70°C unless otherwise noted.)

Characteristic		Symbol	Min	Typ	Max	Unit
Input High Voltage	Enable	V_{IH}	V_{SS} + 2.4	–	V_{CC}	Vdc
	Other Inputs		V_{SS} + 2.0	–	V_{CC}	
Input Low Voltage	Enable	V_{IL}	V_{SS} -0.3	–	V_{SS} + 0.4	Vdc
	Other Inputs		V_{SS} -0.3	–	V_{SS} + 0.8	
Input Leakage Current (V_{in} = 0 to 5.25 Vdc)	R/W, $\overline{Reset}$, RS0, RS1, CS0, CS1, $\overline{CS2}$, CA1, CB1, Enable	I_{in}	–	1.0	2.5	μAdc
Three-State (Off State) Input Current (V_{in} = 0.4 to 2.4 Vdc)	D0-D7, PB0-PB7, CB2	I_{TSI}	–	2.0	10	μAdc
Input High Current (V_{IH} = 2.4 Vdc)	PA0-PA7, CA2	I_{IH}	-100	-250	–	μAdc
Input Low Current (V_{IL} = 0.4 Vdc)	PA0-PA7, CA2	I_{IL}	–	-1.0	-1.6	mAdc
Output High Voltage		V_{OH}				Vdc
(I_{Load} = -205 μAdc, Enable Pulse Width < 25 μs)	D0-D7		V_{SS} + 2.4	–	–	
(I_{Load} = -100 μAdc, Enable Pulse Width <25 μs)	Other Outputs		V_{SS} + 2.4	–	–	
Output Low Voltage (I_{Load} = 1.6 mAdc, Enable Pulse Width < 25 μs)		V_{OL}	–	–	V_{SS} + 0.4	Vdc
Output High Current (Sourcing)		I_{OH}				
(V_{OH} = 2.4 Vdc)	D0-D7		-205	–	–	μAdc
	Other Outputs		-100	–	–	μAdc
(V_O = 1.5 Vdc, the current for driving other than TTL, e.g., Darlington Base)	PB0-PB7, CB2		-1.0	-2.5	-10	mAdc
Output Low Current (Sinking) (V_{OL} = 0.4 Vdc)		I_{OL}	1.6	–	–	mAdc
Output Leakage Current (Off State) (V_{OH} = 2.4 Vdc)	$\overline{IRQA}$, $\overline{IRQB}$	I_{LOH}	–	1.0	10	μAdc
Power Dissipation		P_D	–	–	650	mW
Input Capacitance	Enable	C_{in}	–	–	20	pF
(V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	D0-D7		–	–	12.5	
	PA0-PA7, PB0-PB7, CA2, CB2		–	–	10	
	R/W, $\overline{Reset}$, RS0, RS1, CS0, CS1, $\overline{CS2}$, CA1, CB1		–	–	7.5	
Output Capacitance	$\overline{IRQA}$, $\overline{IRQB}$	C_{out}	–	–	5.0	pF
(V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	PB0-PB7		–	–	10	
Peripheral Data Setup Time (Figure 1)		t_{PDSU}	200	–	–	ns
Delay Time, Enable negative transition to CA2 negative transition (Figure 2, 3)		t_{CA2}	–	–	1.0	μs
Delay Time, Enable negative transition to CA2 positive transition (Figure 2)		t_{RS1}	–	–	1.0	μs
Rise and Fall Times for CA1 and CA2 input signals (Figure 3)		t_r,t_f	–	–	1.0	μs
Delay Time from CA1 active transition to CA2 positive transition (Figure 3)		t_{RS2}	–	–	2.0	μs
Delay Time, Enable negative transition to Peripheral Data valid (Figures 4, 5)		t_{PDW}	–	–	1.0	μs
Delay Time, Enable negative transition to Peripheral CMOS Data Valid (V_{CC} – 30% V_{CC}, Figure 4; Figure 12 Load C)	PA0-PA7, CA2	t_{CMOS}	–	–	2.0	μs
Delay Time, Enable positive transition to CB2 negative transition (Figure 6, 7)		t_{CB2}	–	–	1.0	μs
Delay Time, Paripheral Data valid to CB2 negative transition (Figure 5)		t_{DC}	20	–	–	ns
Delay Time, Enable positive transition to CB2 positive transition (Figure 6)		t_{RS1}	–	–	1.0	μs
Rise and Fall Time for CB1 and CB2 input signals (Figure 7)		t_r,t_f	–	–	1.0	μs
Delay Time, CB1 active transition to CB2 positive transition (Figure 7)		t_{RS2}	–	–	2.0	μs
Interrupt Release Time, $\overline{IRQA}$ and $\overline{IRQB}$ (Figure 8)		t_{IR}	–	–	1.6	μs
Reset Low Time* (Figure 9)		t_{RL}	2.0	–	–	μs

*The Reset line must be high a minimum of 1.0 μs before addressing the PIA.

MC6820

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	V_{CC}	−0.3 to +7.0	Vdc
Input Voltage	V_{in}	−0.3 to +7.0	Vdc
Operating Temperature Range	T_A	0 to +70	°C
Storage Temperature Range	T_{stg}	−55 to +150	°C
Thermal Resistance	θ_{JA}	82.5	°C/W

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

BUS TIMING CHARACTERISTICS

READ (Figures 10 and 12)

Characteristic	Symbol	Min	Typ	Max	Unit
Enable Cycle Time	t_{cycE}	1.0	–	–	µs
Enable Pulse Width, High	PW_{EH}	0.45	–	25	µs
Enable Pulse Width, Low	PW_{EL}	0.43	–	–	µs
Setup Time, Address and R/W valid to Enable positive transition	t_{AS}	160	–	–	ns
Data Delay Time	t_{DDR}	–	–	320	ns
Data Hold Time	t_H	10	–	–	ns
Address Hold Time	t_{AH}	10	–	–	ns
Rise and Fall Time for Enable input	t_{Er}, t_{Ef}	–	–	25	ns

WRITE (Figures 11 and 12)

Enable Cycle Time	t_{cycE}	1.0	–	–	µs
Enable Pulse Width, High	PW_{EH}	0.45	–	25	µs
Enable Pulse Width, Low	PW_{EL}	0.43	–	–	µs
Setup Time, Address and R/W valid to Enable positive transition	t_{AS}	160	–	–	ns
Data Setup Time	t_{DSW}	195	–	–	ns
Data Hold Time	t_H	10	–	–	ns
Address Hold Time	t_{AH}	10	–	–	ns
Rise and Fall Time for Enable input	t_{Er}, t_{Ef}	–	–.	25	ns

FIGURE 1 – PERIPHERAL DATA SETUP TIME
(Read Mode)

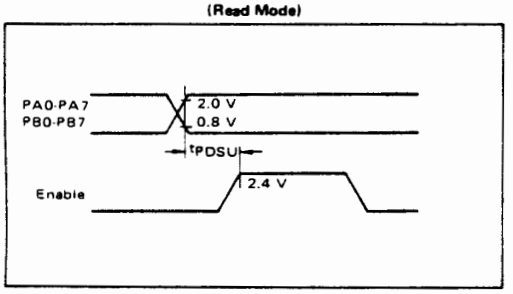
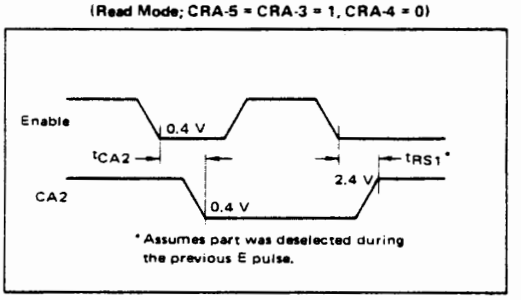
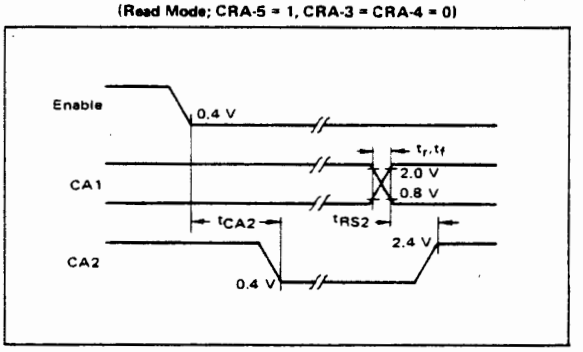


FIGURE 2 – CA2 DELAY TIME
(Read Mode; CRA-5 = CRA-3 = 1, CRA-4 = 0)



*Assumes part was deselected during the previous E pulse.

FIGURE 3 – CA2 DELAY TIME
(Read Mode; CRA-5 = 1, CRA-3 = CRA-4 = 0)



MC6820

FIGURE 4 – PERIPHERAL CMOS DATA DELAY TIMES
(Write Mode; CRA-5 = CRA-3 = 1, CRA-4 = 0)

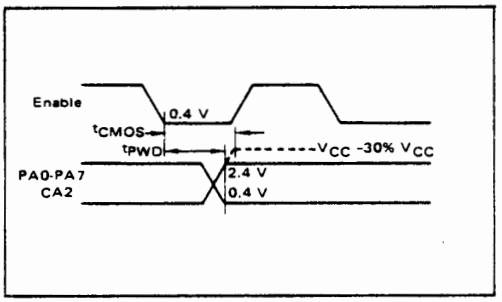


FIGURE 5 – PERIPHERAL DATA AND CB2 DELAY TIMES
(Write Mode; CRB-5 = CRB-3 = 1, CRB-4 = 0)

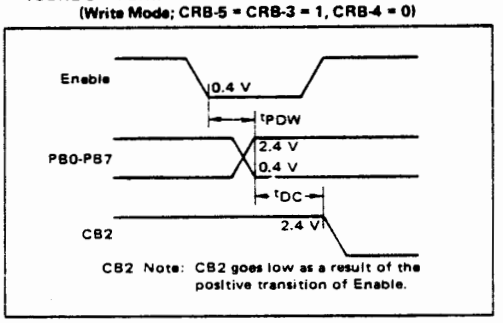


FIGURE 6 – CB2 DELAY TIME
(Write Mode; CRB-5 = CRB-3 = 1, CRB-4 = 0)

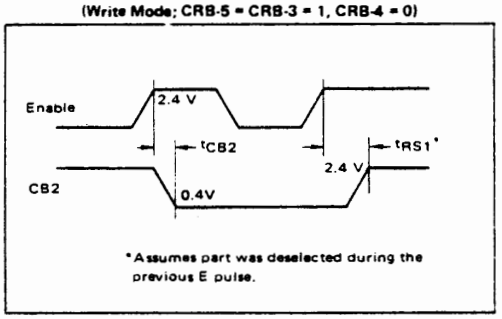


FIGURE 7 – CB2 DELAY TIME
(Write Mode; CRB-5 = 1, CRB-3 = CRB-4 = 0)

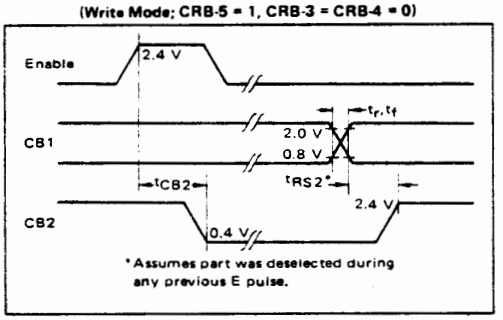


FIGURE 8 – $\overline{IRQ}$ RELEASE TIME

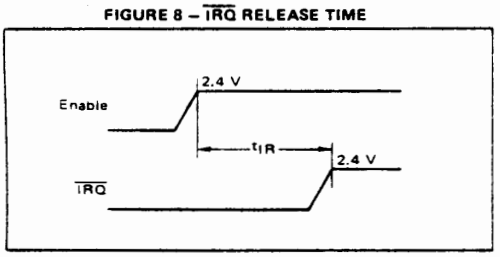


FIGURE 9 – $\overline{RESET}$ LOW TIME

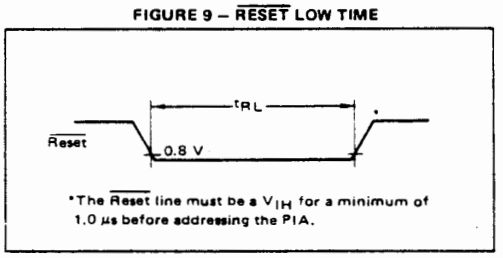


FIGURE 10 – BUS READ TIMING CHARACTERISTICS
(Read Information from PIA)

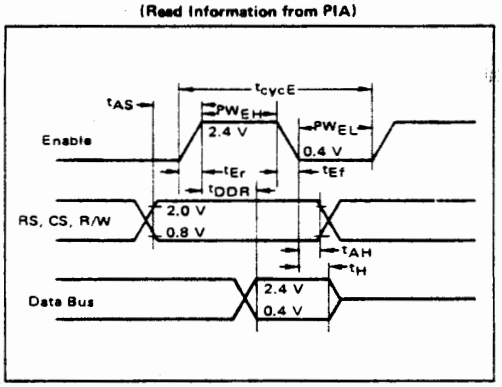


FIGURE 11 – BUS WRITE TIMING CHARACTERISTICS
(Write Information into PIA)

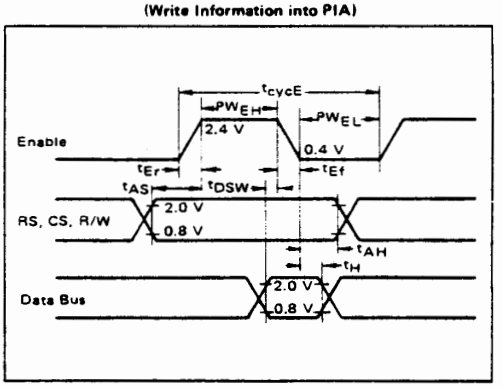
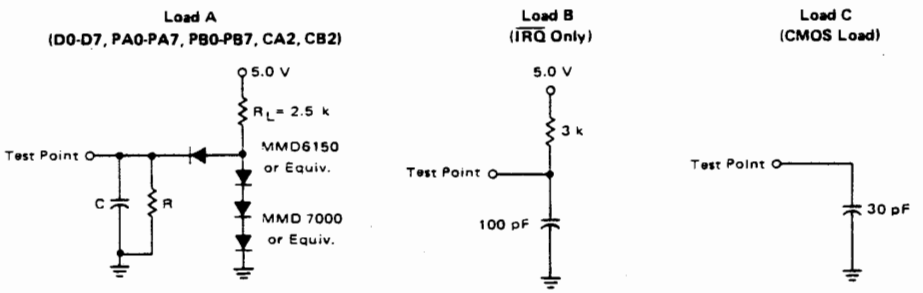


FIGURE 12 – BUS TIMING TEST LOADS



C = 130 pF for D0-D7
= 30 pF for PA0-PA7, PB0-PB7, CA2, and CB2
R = 11.7 kΩ for D0-D7
= 24 kΩ for PA0-PA7, PB0-PB7, CA2 and CB2

PIA INTERFACE SIGNALS FOR MPU

The PIA interfaces to the MC6800 MPU with an eight-bit bi-directional data bus, three chip select lines, two register select lines, two interrupt request lines, read/write line, enable line and reset line. These signals, in conjunction with the MC6800 VMA output, permit the MPU to have complete control over the PIA. VMA should be utilized in conjunction with an MPU address line into a chip select of the PIA.

PIA Bi-Directional Data (D0-D7) – The bi-directional data lines (D0-D7) allow the transfer of data between the MPU and the PIA. The data bus output drivers are three-state devices that remain in the high-impedance (off) state except when the MPU performs a PIA read operation. The Read/Write line is in the Read (high) state when the PIA is selected for a Read operation.

PIA Enable (E) – The enable pulse, E, is the only timing signal that is supplied to the PIA. Timing of all other signals is referenced to the leading and trailing edges of the E pulse. This signal will normally be a derivative of the MC6800 $\phi 2$ Clock.

PIA Read/Write (R/W) – This signal is generated by the MPU to control the direction of data transfers on the Data Bus. A low state on the PIA Read/Write line enables the input buffers and data is transferred from the MPU to the PIA on the E signal if the device has been selected. A high on the Read/Write line sets up the PIA for a transfer of data to the bus. The PIA output buffers are enabled when the proper address and the enable pulse E are present.

$\overline{\text{Reset}}$ – The active low $\overline{\text{Reset}}$ line is used to reset all register bits in the PIA to a logical zero (low). This line can be used as a power-on reset and as a master reset during system operation.

PIA Chip Select (CS0, CS1 and $\overline{\text{CS2}}$) – These three input signals are used to select the PIA. CS0 and CS1 must be high and $\overline{\text{CS2}}$ must be low for selection of the device. Data transfers are then performed under the control of the Enable and Read/Write signals. The chip select lines must be stable for the duration of the E pulse. The device is deselected when any of the chip selects are in the inactive state.

PIA Register Select (RS0 and RS1) – The two register select lines are used to select the various registers inside the PIA. These two lines are used in conjunction with internal Control Registers to select a particular register that is to be written or read.

The register and chip select lines should be stable for the duration of the E pulse while in the read or write cycle.

$\overline{\text{Interrupt Request}}$ ($\overline{\text{IRQA}}$ and $\overline{\text{IRQB}}$) – The active low $\overline{\text{Interrupt Request}}$ lines ($\overline{\text{IRQA}}$ and $\overline{\text{IRQB}}$) act to interrupt the MPU either directly or through interrupt priority circuitry. These lines are "open drain" (no load device on the chip). This permits all interrupt request lines to be tied together in a wire-OR configuration.

Each $\overline{\text{Interrupt Request}}$ line has two internal interrupt flag bits that can cause the $\overline{\text{Interrupt Request}}$ line to go low. Each flag bit is associated with a particular peripheral interrupt line. Also four interrupt enable bits are provided in the PIA which may be used to inhibit a particular interrupt from a peripheral device.

Servicing an interrupt by the MPU may be accomplished by a software routine that, on a prioritized basis, sequentially reads and tests the two control registers in each PIA for interrupt flag bits that are set.

The interrupt flags are cleared (zeroed) as a result of an

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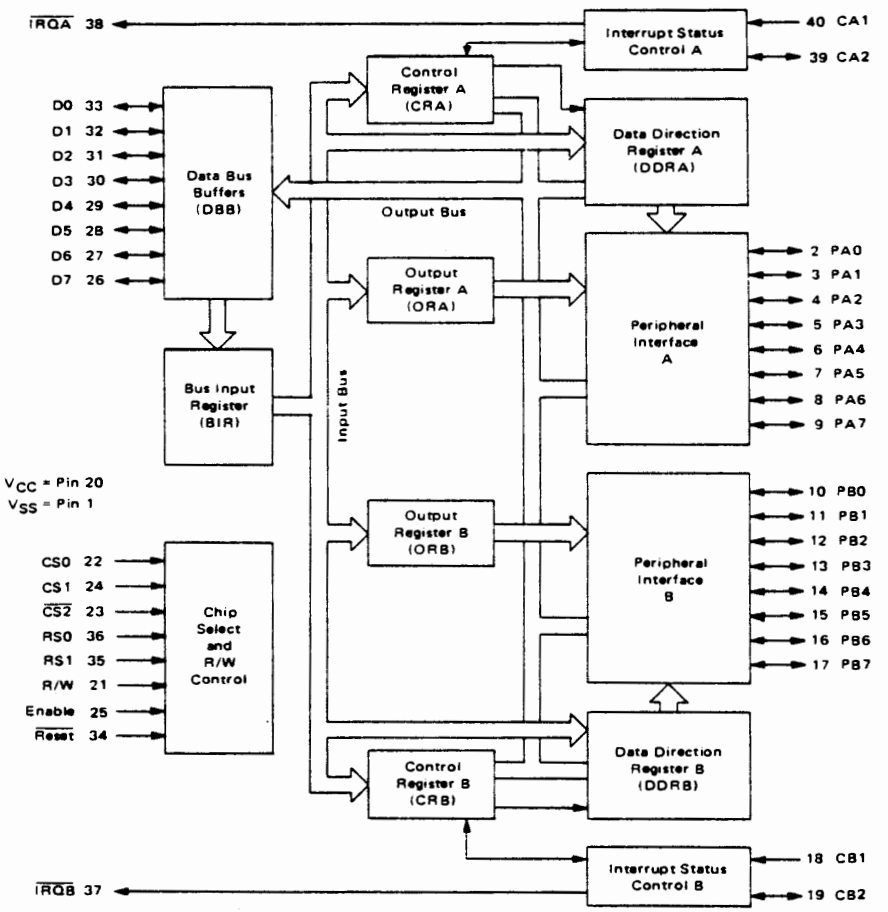
EXPANDED BLOCK DIAGRAM



MPU Read Peripheral Data Operation of the corresponding data register. After being cleared, the interrupt flag bit cannot be enabled to be set until the PIA is deselected during an E pulse. The E pulse is used to condition the interrupt control lines (CA1, CA2, CB1, CB2). When these lines are used as interrupt inputs at least one E pulse must occur from the inactive edge to the active edge of the interrupt input signal to condition the edge sense network. If the interrupt flag has been enabled and the edge sense circuit has been properly conditioned, the interrupt flag will be set on the next active transition of the interrupt input pin.

PIA PERIPHERAL INTERFACE LINES

The PIA provides two 8-bit bi-directional data buses and four interrupt/control lines for interfacing to peripheral devices.

Section A Peripheral Data (PA0-PA7) – Each of the peripheral data lines can be programmed to act as an input or output. This is accomplished by setting a "1" in the corresponding Data Direction Register bit for those lines which are to be outputs. A "0" in a bit of the Data Direction Register causes the corresponding peripheral data line to act as an input. During an MPU Read Peripheral Data Operation, the data on peripheral lines programmed to act as inputs appears directly on the corresponding MPU Data Bus lines. In the input mode the internal pullup resistor on these lines represents a maximum of one standard TTL load.

The data in Output Register A will appear on the data lines that are programmed to be outputs. A logical "1" written into the register will cause a "high" on the corresponding data line while a "0" results in a "low". Data in Output Register A may be read by an MPU "Read Peripheral Data A" operation when the corresponding lines are programmed as outputs. This data will be read properly if the voltage on the peripheral data lines is greater than 2.0 volts for a logic "1" output and less than 0.8 volt for a logic "0" output. Loading the output lines such that the voltage on these lines does not reach full voltage causes the data transferred into the MPU on a Read operation to differ from that contained in the respective bit of Output Register A.

Section B Peripheral Data (PB0-PB7) – The peripheral data lines in the B Section of the PIA can be programmed to act as either inputs or outputs in a similar manner to PA0-PA7. However, the output buffers driving these lines differ from those driving lines PA0-PA7. They have three-state capability, allowing them to enter a high impedance state when the peripheral data line is used as an input. In addition, data on the peripheral data lines PB0-PB7 will be read properly from those lines programmed as outputs even if the voltages are below 2.0 volts for a "high". As outputs, these lines are compatible with standard TTL and may also be used as a source of up to 1 milliampere at 1.5 volts to directly drive the base of a transistor switch.

Interrupt Input (CA1 and CB1) – Peripheral Input lines CA1 and CB1 are input only lines that set the interrupt flags of the control registers. The active transition for these signals is also programmed by the two control registers.

Peripheral Control (CA2) – The peripheral control line CA2 can be programmed to act as an interrupt input or as a peripheral control output. As an output, this line is compatible with standard TTL; as an input the internal pullup resistor on this line represents one standard TTL load. The function of this signal line is programmed with Control Register A.

Peripheral Control (CB2) – Peripheral Control line CB2 may also be programmed to act as an interrupt input or peripheral control output. As an input, this line has high input impedance and is compatible with standard TTL. As an output it is compatible with standard TTL and may also be used as a source of up to 1 milliampere at 1.5 volts to directly drive the base of a transistor switch. This line is programmed by Control Register B.

NOTE: It is recommended that the control lines (CA1, CA2, CB1, CB2) should be held in a logic 1 state when $\overline{\text{Reset}}$ is active to prevent setting of corresponding interrupt flags in the control register when $\overline{\text{Reset}}$ goes to an inactive state. Subsequent to $\overline{\text{Reset}}$ going inactive, a read of the data registers may be used to clear any undesired interrupt flags.

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INTERNAL CONTROLS

There are six locations within the PIA accessible to the MPU data bus: two Peripheral Registers, two Data Direction Registers, and two Control Registers. Selection of these locations is controlled by the RS0 and RS1 inputs together with bit 2 in the Control Register, as shown in Table 1.

TABLE 1 – INTERNAL ADDRESSING

RS1	RS0	Control Register Bit CRA-2	Control Register Bit CRB-2	Location Selected
0	0	1	X	Peripheral Register A
0	0	0	X	Data Direction Register A
0	1	X	X	Control Register A
1	0	X	1	Peripheral Register B
1	0	X	0	Data Direction Register B
1	1	X	X	Control Register B

X = Don't Care

INITIALIZATION

A low reset line has the effect of zeroing all PIA registers. This will set PA0-PA7, PB0-PB7, CA2 and CB2 as inputs, and all interrupts disabled. The PIA must be configured during the restart program which follows the reset.

Details of possible configurations of the Data Direction and Control Register are as follows.

DATA DIRECTION REGISTERS (DDRA and DDRB)

The two Data Direction Registers allow the MPU to control the direction of data through each corresponding peripheral data line. A Data Direction Register bit set at "0" configures the corresponding peripheral data line as an input; a "1" results in an output.

CONTROL REGISTERS (CRA and CRB)

The two Control Registers (CRA and CRB) allow the MPU to control the operation of the four peripheral control lines CA1, CA2, CB1 and CB2. In addition they allow the MPU to enable the interrupt lines and monitor the status of the interrupt flags. Bits 0 through 5 of the two registers may be written or read by the MPU when the proper chip select and register select signals are applied. Bits 6 and 7 of the two registers are read only and are modified by external interrupts occurring on control lines CA1, CA2, CB1 or CB2. The format of the control words is shown in Table 2.

TABLE 2 – CONTROL WORD FORMAT

	7	6	5	4	3	2	1	0
CRA	IRQA1	IRQA2	CA2 Control			DDRA Access	CA1 Control	
CRB	IRQB1	IRQB2	CB2 Control			DDRB Access	CB1 Control	

Data Direction Access Control Bit (CRA-2 and CRB-2) – Bit 2 in each Control register (CRA and CRB) allows selection of either a Peripheral Interface Register or the Data Direction Register when the proper register select signals are applied to RS0 and RS1.

Interrupt Flags (CRA-6, CRA-7, CRB-6, and CRB-7) – The four interrupt flag bits are set by active transitions of signals on the four Interrupt and Peripheral Control lines when those lines are programmed to be inputs. These bits cannot be set directly from the MPU Data Bus and are reset indirectly by a Read Peripheral Data Operation on the appropriate section.

TABLE 3 – CONTROL OF INTERRUPT INPUTS CA1 AND CB1

CRA-1 (CRB-1)	CRA-0 (CRB-0)	Interrupt Input CA1 (CB1)	Interrupt Flag CRA-7 (CRB-7)	MPU Interrupt Request $\overline{IRQA}$ ($\overline{IRQB}$)
0	0	↓ Active	Set high on ↓ of CA1 (CB1)	Disabled — $\overline{IRQ}$ remains high
0	1	↓ Active	Set high on ↓ of CA1 (CB1)	Goes low when the interrupt flag bit CRA-7 (CRB-7) goes high
1	0	↑ Active	Set high on ↑ of CA1 (CB1)	Disabled — $\overline{IRQ}$ remains high
1	1	↑ Active	Set high on ↑ of CA1 (CB1)	Goes low when the interrupt flag bit CRA-7 (CRB-7) goes high

Notes: 1. ↑ indicates positive transition (low to high)

2. ↓ indicates negative transition (high to low)

3. The Interrupt flag bit CRA-7 is cleared by an MPU Read of the A Data Register, and CRB-7 is cleared by an MPU Read of the B Data Register.

4. If CRA-0 (CRB-0) is low when an interrupt occurs (Interrupt disabled) and is later brought high, $\overline{IRQA}$ ($\overline{IRQB}$) occurs after CRA-0 (CRB-0) is written to a "one".

Control of CA1 and CB1 Interrupt Input Lines (CRA-0, CRB-0, CRA-1, and CRB-1) – The two lowest order bits of the control registers are used to control the interrupt input lines CA1 and CB1. Bits CRA-0 and CRB-0 are used to enable the MPU interrupt signals $\overline{IRQA}$ and $\overline{IRQB}$, respectively. Bits CRA-1 and CRB-1 determine the active transition of the interrupt input signals CA1 and CB1 (Table 3).

TABLE 4 – CONTROL OF CA2 AND CB2 AS INTERRUPT INPUTS
CRA5 (CRB5) is low

CRA-5 (CRB-5)	CRA-4 (CRB-4)	CRA-3 (CRB-3)	Interrupt Input CA2 (CB2)	Interrupt Flag CRA-6 (CRB-6)	MPU Interrupt Request $\overline{IRQA}$ ($\overline{IRQB}$)
0	0	0	↓ Active	Set high on ↓ of CA2 (CB2)	Disabled — $\overline{IRQ}$ remains high
0	0	1	↓ Active	Set high on ↓ of CA2 (CB2)	Goes low when the interrupt flag bit CRA-6 (CRB-6) goes high
0	1	0	↑ Active	Set high on ↑ of CA2 (CB2)	Disabled — $\overline{IRQ}$ remains high
0	1	1	↑ Active	Set high on ↑ of CA2 (CB2)	Goes low when the interrupt flag bit CRA-6 (CRB-6) goes high

Notes: 1. ↑ indicates positive transition (low to high)

2. ↓ indicates negative transition (high to low)

3. The interrupt flag bit CRA-6 is cleared by an MPU Read of the A Data Register and CRB-6 is cleared by an MPU Read of the B Data Register.

4. If CRA-3 (CRB-3) is low when an interrupt occurs (Interrupt disabled) and is later brought high, $\overline{IRQA}$ ($\overline{IRQB}$) occurs after CRA-3 (CRB-3) is written to a "one".

TABLE 5 – CONTROL OF CB2 AS AN OUTPUT
CRB-5 is high

CRB-5	CRB-4	CRB-3	CB2	
			Cleared	Set
1	0	0	Low on the positive transition of the first E pulse following an MPU Write "B" Data Register operation.	High when the interrupt flag bit CRB-7 is set by an active transition of the CB1 signal.
1	0	1	Low on the positive transition of the first E pulse after an MPU Write "B" Data Register operation.	High on the positive edge of the first "E" pulse following an "E" pulse which occurred while the part was deselected.
1	1	0	Low when CRB-3 goes low as a result of an MPU Write in Control Register "B".	Always low as long as CRB-3 is low. Will go high on an MPU Write in Control Register "B" that changes CRB-3 to "one".
1	1	1	Always high as long as CRB-3 is high. Will be cleared when an MPU Write Control Register "B" results in clearing CRB-3 to "zero".	High when CRB-3 goes high as a result of an MPU Write into Control Register "B".

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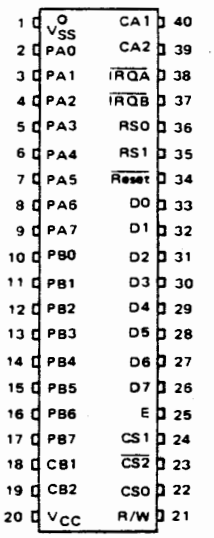
Control of CA2 and CB2 Peripheral Control Lines (CRA-3, CRA-4, CRA-5, CRB-3, CRB-4, and CRB-5) – Bits 3, 4, and 5 of the two control registers are used to control the CA2 and CB2 Peripheral Control lines. These bits determine if the control lines will be an interrupt input or an output control signal. If bit CRA-5 (CRB-5) is low, CA2 (CB2) is an interrupt input line similar to CA1 (CB1) (Table 4). When CRA-5 (CRB-5) is high, CA2 (CB2) becomes an output signal that may be used to control peripheral data transfers. When in the output mode, CA2 and CB2 have slightly different characteristics (Tables 5 and 6).

TABLE 6 – CONTROL OF CA-2 AS AN OUTPUT
CRA-5 is high

CRA-5	CRA-4	CRA-3	CA2 Cleared	CA2 Set
1	0	0	Low on negative transition of E after an MPU Read "A" Data operation.	High when the interrupt flag bit CRA-7 is set by an active transition of the CA1 signal.
1	0	1	Low on negative transition of E after an MPU Read "A" Data operation.	High on the negative edge of the first "E" pulse which occurs during a deselect.
1	1	0	Low when CRA-3 goes low as a result of an MPU Write to Control Register "A".	Always low as long as CRA-3 is low. Will go high on an MPU Write to Control Register "A" that changes CRA-3 to "one".
1	1	1	Always high as long as CRA-3 is high. Will be cleared on an MPU Write to Control Register "A" that clears CRA-3 to a "zero".	High when CRA-3 goes high as a result of an MPU Write to Control Register "A".

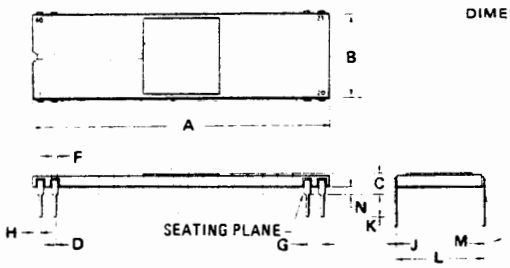
PIN ASSIGNMENT



PACKAGE DIMENSIONS

CASE 715-02
(CERAMIC)

SEE PAGE 165 FOR PLASTIC PACKAGE DIMENSIONS.



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	50.29	51.31	1.980	2.020
B	14.86	15.62	0.585	0.615
C	2.54	4.19	0.100	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.40	0.030	0.055
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.33	0.008	0.013
K	2.54	4.19	0.100	0.165
L	14.60	15.37	0.575	0.605
M	–	10°	–	10°
N	0.51	1.52	0.020	0.060

NOTE:
1. LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIA (AT SEATING PLANE), AT MAX. MAT'L CONDITION.

MOTOROLA Semiconductors
BOX 20912 • PHOENIX, ARIZONA 85036

MC6850

(0 to 70°C; L or P Suffix)

MC6850C

(-40 to 85°C; L Suffix only)

ASYNCHRONOUS COMMUNICATIONS INTERFACE ADAPTER (ACIA)

The MC6850 Asynchronous Communications Interface Adapter provides the data formatting and control to interface serial asynchronous data communications information to bus organized systems such as the MC6800 Microprocessing Unit.

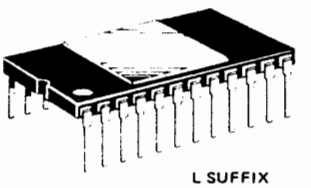
The bus interface of the MC6850 includes select, enable, read/write, interrupt and bus interface logic to allow data transfer over an 8-bit bi-directional data bus. The parallel data of the bus system is serially transmitted and received by the asynchronous data interface, with proper formatting and error checking. The functional configuration of the ACIA is programmed via the data bus during system initialization. A programmable Control Register provides variable word lengths, clock division ratios, transmit control, receive control, and interrupt control. For peripheral or modem operation three control lines are provided. These lines allow the ACIA to interface directly with the MC6860L 0-600 bps digital modem.

- Eight and Nine-Bit Transmission
- Optional Even and Odd Parity
- Parity, Overrun and Framing Error Checking
- Programmable Control Register
- Optional ÷1, ÷16, and ÷64 Clock Modes
- Up to 500 kbps Transmission
- False Start Bit Deletion
- Peripheral/Modem Control Functions
- Double Buffered
- One or Two Stop Bit Operation

MOS

(N-CHANNEL, SILICON-GATE)

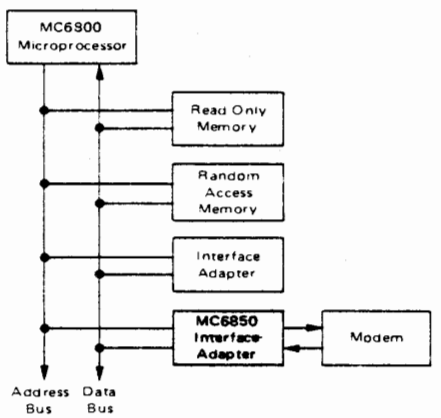
ASYNCHRONOUS COMMUNICATIONS INTERFACE ADAPTER



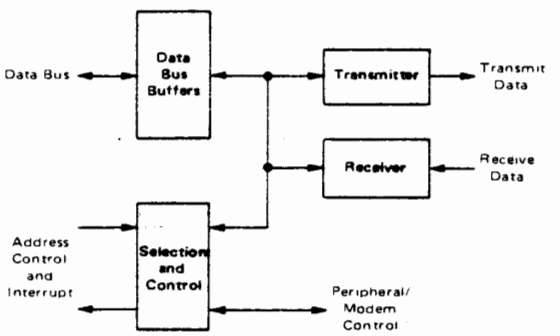
L SUFFIX
CERAMIC PACKAGE
CASE 716

NOT SHOWN: P SUFFIX
PLASTIC PACKAGE
CASE 709

M6800 MICROCOMPUTER FAMILY BLOCK DIAGRAM



MC6850 ASYNCHRONOUS COMMUNICATIONS INTERFACE ADAPTER BLOCK DIAGRAM



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	V_{CC}	-0.3 to +7.0	Vdc
Input Voltage	V_{in}	-0.3 to +7.0	Vdc
Operating Temperature Range	T_A	0 to +70	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C
Thermal Resistance	θ_{JA}	82.5	°C/W

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

ELECTRICAL CHARACTERISTICS (V_{CC} = 5.0 V ±5%, V_{SS} = 0, T_A = 0 to 70°C unless otherwise noted.)

Characteristic		Symbol	Min	Typ	Max	Unit
Input High Voltage		V_{IH}	V_{SS} + 2.0	–	V_{CC}	Vdc
Input Low Voltage		V_{IL}	V_{SS} -0.3	–	V_{SS} + 0.8	Vdc
Input Leakage Current (V_{in} = 0 to 5.25 Vdc)	R/W,CS0,CS1,$\overline{CS2}$,Enable	I_{in}	–	1.0	2.5	µAdc
Three-State (Off State) Input Current (V_{in} = 0.4 to 2.4 Vdc)	D0-D7	I_{TSI}	–	2.0	10	µAdc
Output High Voltage	D0-D7	V_{OH}				Vdc
(I_{Load} = -205 µAdc, Enable Pulse Width <25 µs)			V_{SS} + 2.4	–	–	
(I_{Load} = -100 µAdc, Enable Pulse Width <25 µs)	Tx Data, $\overline{RTS}$		V_{SS} + 2.4	–	–	
Output Low Voltage (I_{Load} = 1.6 mAdc, Enable Pulse Width <25 µs)		V_{OL}	–	–	V_{SS} + 0.4	Vdc
Output Leakage Current (Off State) (V_{OH} = 2.4 Vdc)	$\overline{IRQ}$	I_{LOH}	–	1.0	10	µAdc
Power Dissipation		P_D	–	300	525	mW
Input Capacitance		C_{in}				pF
(V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	D0-D7		–	10	12.5	
E, Tx Clk, Rx Clk, R/W, RS, Rx Data, CS0, CS1, $\overline{CS2}$, $\overline{CTS}$, $\overline{DCD}$			–	7.0	7.5	
Output Capacitance	$\overline{RTS}$, Tx Data	C_{out}	–	–	10	pF
(V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	$\overline{IRQ}$		–	–	5.0	
Minimum Clock Pulse Width, Low (Figure 1)	÷16, ÷64 Modes	PW_{CL}	600	–	–	ns
Minimum Clock Pulse Width, High (Figure 2)	÷16, ÷64 Modes	PW_{CH}	600	–	–	ns
Clock Frequency	÷1 Mode	f_C	–	–	500	kHz
	÷16, ÷64 Modes		–	–	800	
Clock-to-Data Delay for Transmitter (Figure 3)		t_{TDD}	–	–	1.0	µs
Receive Data Setup Time (Figure 4)	÷1 Mode	t_{RDSU}	500	–	–	ns
Receive Data Hold Time (Figure 5)	÷1 Mode	t_{RDH}	500	–	–	ns
$\overline{Interrupt\ Request}$ Release Time (Figure 6)		t_{IR}	–	–	1.2	µs
$\overline{Request\text{-}to\text{-}Send}$ Delay Time (Figure 6)		t_{RTS}	–	–	1.0	µs
Input Transition Times (Except Enable)		t_r, t_f	–	–	1.0*	µs

*1.0 µs or 10% of the pulse width, whichever is smaller.

BUS TIMING CHARACTERISTICS

READ (Figures 7 and 9)

Characteristic	Symbol	Min	Typ	Max	Unit
Enable Cycle Time	t_{cycE}	1.0	–	–	µs
Enable Pulse Width, High	PW_{EH}	0.45	–	25	µs
Enable Pulse Width, Low	PW_{EL}	0.43	–	–	µs
Setup Time, Address and R/W valid to Enable positive transition	t_{AS}	160	–	–	ns
Data Delay Time	t_{DDR}	–	–	320	ns
Data Hold Time	t_H	10	–	–	ns
Address Hold Time	t_{AH}	10	–	–	ns
Rise and Fall Time for Enable input	t_{Er}, t_{Ef}	–	–	25	ns

WRITE (Figure 8 and 9)

Enable Cycle Time	t_{cycE}	1.0	–	–	µs
Enable Pulse Width, High	PW_{EH}	0.45	–	25	µs
Enable Pulse Width, Low	PW_{EL}	0.43	–	–	µs
Setup Time, Address and R/W valid to Enable positive transition	t_{AS}	160	–	–	ns
Data Setup Time	t_{DSW}	195	–	–	ns
Data Hold Time	t_H	10	–	–	ns
Address Hold Time	t_{AH}	10	–	–	ns
Rise and Fall Time for Enable input	t_{Er}, t_{Ef}	–	–	25	ns

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FIGURE 1 – CLOCK PULSE WIDTH, LOW-STATE

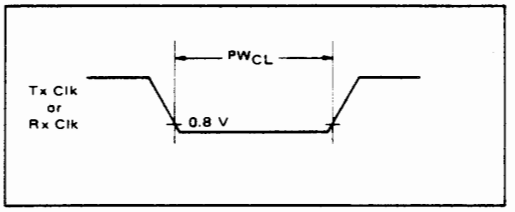


FIGURE 2 – CLOCK PULSE WIDTH, HIGH-STATE

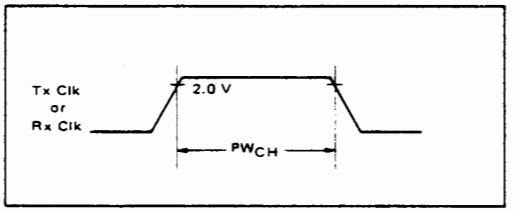


FIGURE 3 – TRANSMIT DATA OUTPUT DELAY

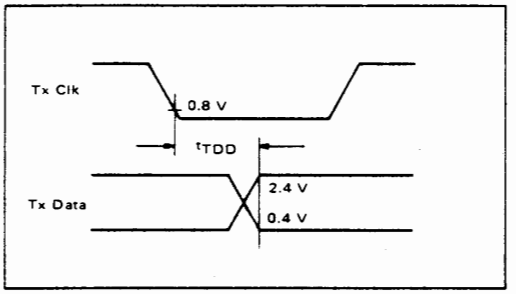


FIGURE 4 – RECEIVE DATA SETUP TIME
(÷1 Mode)

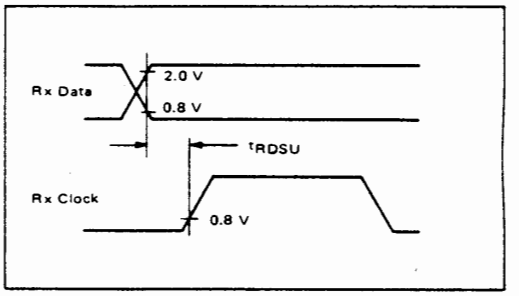


FIGURE 5 – RECEIVE DATA HOLD TIME
(÷1 Mode)

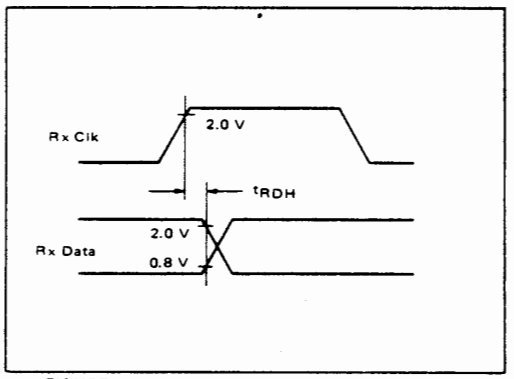


FIGURE 6 – $\overline{\text{REQUEST-TO-SEND}}$ DELAY AND $\overline{\text{INTERRUPT-REQUEST}}$ RELEASE TIMES

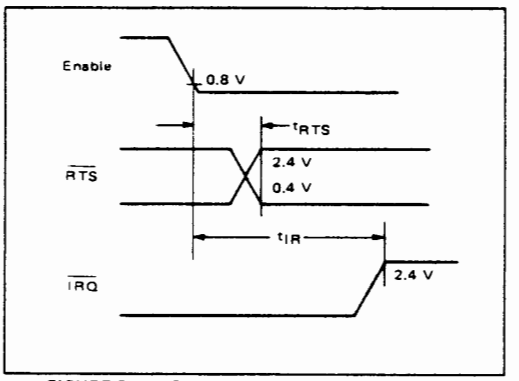


FIGURE 7 – BUS READ TIMING CHARACTERISTICS
(Read information from ACIA)

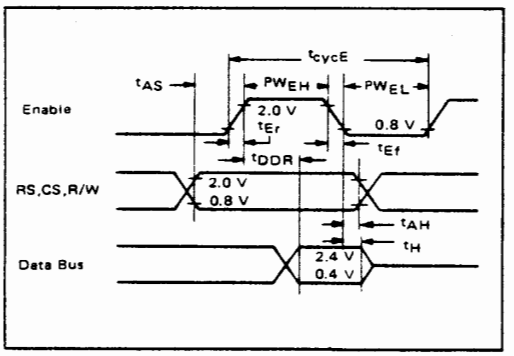


FIGURE 8 – BUS WRITE TIMING CHARACTERISTICS
(Write information into ACIA)

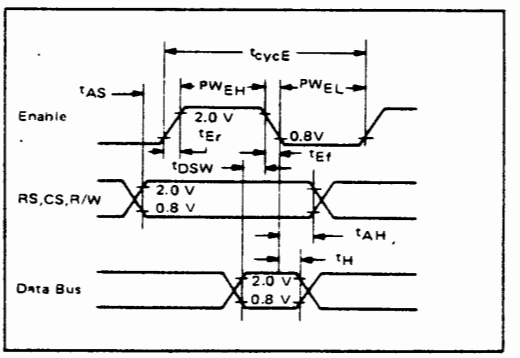
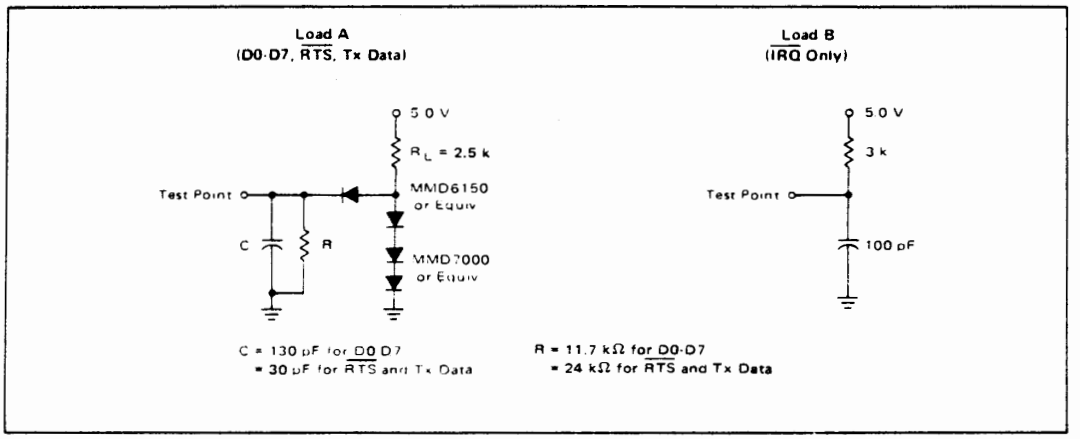
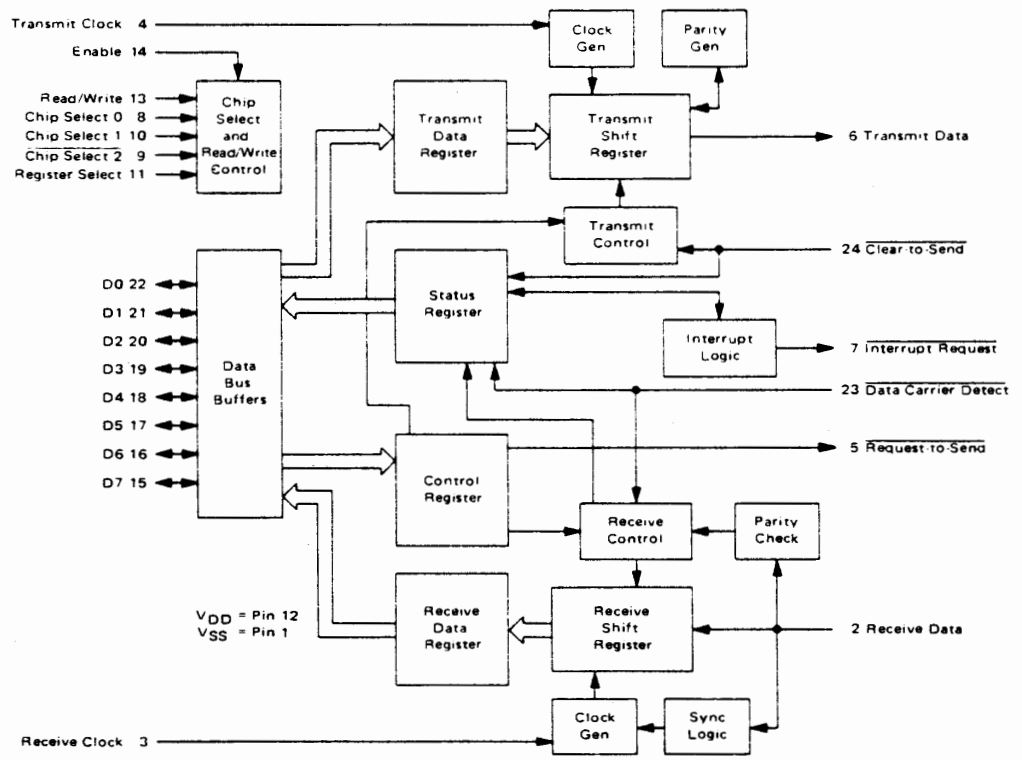


FIGURE 9 – BUS TIMING TEST LOADS



EXPANDED BLOCK DIAGRAM



DEVICE OPERATION

At the bus interface, the ACIA appears as two addressable memory locations. Internally, there are four registers: two read-only and two write-only registers. The read-only registers are Status and Receive Data; the write-only registers are Control and Transmit Data. The serial interface consists of serial input and output lines with independent clocks, and three peripheral/modem control lines.

POWER ON/MASTER RESET

The master reset (CR0, CR1) should be set during system initialization to insure the reset condition and prepare for programming the ACIA functional configuration when the communications channel is required. Control bits CR5 and CR6 should also be programmed to define the state of $\overline{RTS}$ whenever master reset is utilized. The ACIA also contains internal power-on reset logic to detect the power line turn-on transition and hold the chip in a reset state to prevent erroneous output transitions prior to initialization. This circuitry depends on clean power turn-on transitions. The power-on reset is released by means of the bus-programmed master reset which must be applied prior to operating the ACIA. After master resetting the ACIA, the programmable Control Register can be set for a number of options such as variable clock divider ratios, variable word length, one or two stop bits, parity (even, odd, or none), etc.

TRANSMIT

A typical transmitting sequence consists of reading the ACIA Status Register either as a result of an interrupt or in the ACIA's turn in a polling sequence. A character may be written into the Transmit Data Register if the status read operation has indicated that the Transmit Data Register is empty. This character is transferred to a Shift Register where it is serialized and transmitted from the Transmit Data output preceded by a start bit and followed by one or two stop bits. Internal parity (odd or even) can be optionally added to the character and will occur between the last data bit and the first stop bit. After the first character is written in the Data Register, the Status Register can be read again to check for a Transmit Data Register Empty condition and current peripheral status. If the register is empty, another character can be loaded for transmission even though the first character is in the process of being transmitted (because of double buffering). The second character will be automatically transferred into the Shift Register when the first character transmission is completed. This sequence continues until all the characters have been transmitted.

RECEIVE

Data is received from a peripheral by means of the Receive Data input. A divide-by-one clock ratio is provided for an externally synchronized clock (to its data) while the divide-by-16 and 64 ratios are provided for internal synchronization. Bit synchronization in the divide-by-16 and 64 modes is initiated by the detection of the leading mark-to-space transition of the start bit. False start bit deletion capability insures that a full half bit of a start bit has been received before the internal clock is synchronized to the bit time. As a character is being received, parity (odd or even) will be checked and the error indication will be available in the Status Register along with framing error, overrun error, and Receive Data Register full. In a typical receiving sequence, the Status Register is read to determine if a character has been received from a peripheral. If the Receiver Data Register is full, the character is placed on the 8-bit ACIA bus when a Read Data command is received from the MPU. When parity has been selected for an 8-bit word (7 bits plus parity), the receiver strips the parity bit (D7 = 0) so that data alone is transferred to the MPU. This feature reduces MPU programming. The Status Register can continue to be read again to determine when another character is available in the Receive Data Register. The receiver is also double buffered so that a character can be read from the data register as another character is being received in the shift register. The above sequence continues until all characters have been received.

INPUT/OUTPUT FUNCTIONS

ACIA INTERFACE SIGNALS FOR MPU

The ACIA interfaces to the MC6800 MPU with an 8-bit bi-directional data bus, three chip select lines, a register select line, an interrupt request line, read/write line, and enable line. These signals, in conjunction with the MC6800 VMA output, permit the MPU to have complete control over the ACIA.

ACIA Bi-Directional Data (D0-D7) – The bi-directional data lines (D0-D7) allow for data transfer between the ACIA and the MPU. The data bus output drivers are three-state devices that remain in the high-impedance (off) state except when the MPU performs an ACIA read operation.

ACIA Enable (E) – The Enable signal, E, is a high impedance TTL compatible input that enables the bus input output data buffers and clocks data to and from the ACIA. This signal will normally be a derivative of the MC6800 $\phi 2$ Clock.

Read/Write (R/W) – The Read Write line is a high impedance input that is TTL compatible and is used to control the direction of data flow through the ACIA's input output data bus interface. When Read/Write is high (MPU Read cycle), ACIA output drivers are turned on and a selected register is read. When it is low, the ACIA output drivers are turned off and the MPU writes into a selected register. Therefore, the Read/Write signal is used to select read-only or write-only registers within the ACIA.

Chip Select (CS0, CS1, $\overline{CS2}$) – These three high impedance TTL compatible input lines are used to address the ACIA. The ACIA is selected when CS0 and CS1 are high and $\overline{CS2}$ is low. Transfers of data to and from the ACIA are then performed under the control of the Enable signal, Read/Write, and Register Select.

Register Select (RS) – The Register Select line is a high impedance input that is TTL compatible. A high level is used to select the Transmit/Receive Data Registers and a low level the Control/Status Registers. The Read/Write signal line is used in conjunction with Register Select to select the read-only or write-only register in each register pair.

$\overline{\text{Interrupt Request}}$ ($\overline{IRQ}$) – $\overline{\text{Interrupt Request}}$ is a TTL compatible, open-drain (no internal pullup), active low

output that is used to interrupt the MPU. The $\overline{IRQ}$ output remains low as long as the cause of the interrupt is present and the appropriate interrupt enable within the ACIA is set. The IRQ status bit, when high, indicates the $\overline{IRQ}$ output is in the active state.

Interrupts result from conditions in both the transmitter and receiver sections of the ACIA. The transmitter section causes an interrupt when the Transmitter Interrupt Enabled condition is selected (CR5 · $\overline{CR6}$), and the Transmit Data Register Empty (TDRE) status bit is high. The TDRE status bit indicates the current status of the Transmitter Data Register except when inhibited by Clear-to-Send ($\overline{CTS}$) being high or the ACIA being maintained in the Reset condition. The interrupt is cleared by writing data into the Transmit Data Register. The interrupt is masked by disabling the Transmitter Interrupt via CR5 or CR6 or by the loss of $\overline{CTS}$ which inhibits the TDRE status bit. The Receiver section causes an interrupt when the Receiver Interrupt Enable is set and the Receive Data Register Full (RDRF) status bit is high, an Overrun has occurred, or Data Carrier Detect ($\overline{DCD}$) has gone high. An interrupt resulting from the RDRF status bit can be cleared by reading data or resetting the ACIA. Interrupts caused by Overrun or loss of $\overline{DCD}$ are cleared by reading the status register after the error condition has occurred and then reading the Receive Data Register or resetting the ACIA. The receiver interrupt is masked by resetting the Receiver Interrupt Enable.

CLOCK INPUTS

Separate high impedance TTL compatible inputs are provided for clocking of transmitted and received data. Clock frequencies of 1, 16 or 64 times the data rate may be selected.

Transmit Clock (Tx Clk) – The Transmit Clock input is used for the clocking of transmitted data. The transmitter initiates data on the negative transition of the clock.

Receive Clock (Rx Clk) – The Receive Clock input is used for synchronization of received data. (In the ÷ 1 mode, the clock and data must be synchronized externally.) The receiver samples the data on the positive transiton of the clock.

SERIAL INPUT/OUTPUT LINES

Receive Data (Rx Data) – The Receive Data line is a high impedance TTL compatible input through which data is received in a serial format. Synchronization with a clock for detection of data is accomplished internally when clock rates of 16 or 64 times the bit rate are used. Data rates are in the range of 0 to 500 kbps when external synchronization is utilized.

Transmit Data (Tx Data) – The Transmit Data output line transfers serial data to a modem or other peripheral. Data rates are in the range of 0 to 500 kbps when external synchronization is utilized.

PERIPHERAL/MODEM CONTROL

The ACIA includes several functions that permit limited control of a peripheral or modem. The functions included are Clear-to-Send, Request-to-Send and Data Carrier Detect.

Clear-to-Send ($\overline{CTS}$) – This high impedance TTL compatible input provides automatic control of the transmitting end of a communications link via the modem Clear-to-Send active low output by inhibiting the Transmit Data Register Empty (TDRE) status bit.

Request-to-Send ($\overline{RTS}$) – The Request-to-Send output enables the MPU to control a peripheral or modem via the data bus. The $\overline{RTS}$ output corresponds to the state of the Control Register bits CR5 and CR6. When CR6 = 0 or both CR5 and CR6 = 1, the $\overline{RTS}$ output is low (the active state). This output can also be used for Data Terminal Ready ($\overline{DTR}$).

Data Carrier Detect ($\overline{DCD}$) – This high impedance TTL compatible input provides automatic control, such as in the receiving end of a communications link by means of a modem Data Carrier Detect output. The $\overline{DCD}$ input inhibits and initializes the receiver section of the ACIA when high. A low to high transition of the Data Carrier Detect initiates an interrupt to the MPU to indicate the occurrence of a loss of carrier when the Receive Interrupt Enable bit is set.

ACIA REGISTERS

The expanded block diagram for the ACIA indicates the internal registers on the chip that are used for the status, control, receiving, and transmitting of data. The content of each of the registers is summarized in Table 1.

TRANSMIT DATA REGISTER (TDR)

Data is written in the Transmit Data Register during the negative transition of the enable (E) when the ACIA has been addressed and RS · $\overline{R/W}$ is selected. Writing data into the register causes the Transmit Data Register Empty bit in the Status Register to go low. Data can then be transmitted. If the transmitter is idling and no character is being transmitted, then the transfer will take place within one bit time of the trailing edge of the Write command. If a character is being transmitted, the new data character will commence as soon as the previous character is complete. The transfer of data causes the Transmit Data Register Empty (TDRE) bit to indicate empty.

RECEIVE DATA REGISTER (RDR)

Data is automatically transferred to the empty Receive Data Register (RDR) from the receiver deserializer (a shift register) upon receiving a complete character. This event causes the Receive Data Register Full bit (RDRF) in the status buffer to go high (full). Data may then be read through the bus by addressing the ACIA and selecting the Receive Data Register with RS and R/W high when the ACIA is enabled. The non-destructive read cycle causes the RDRF bit to be cleared to empty although

TABLE 1 – DEFINITION OF ACIA REGISTER CONTENTS

Data Bus Line Number	Buffer Address			
	RS • $\overline{R/W}$ Transmit Data Register (Write Only)	RS • R/W Receive Data Register (Read Only)	$\overline{RS}$ • $\overline{R/W}$ Control Register (Write Only)	$\overline{RS}$ • R/W Status Register (Read Only)
0	Data Bit 0*	Data Bit 0	Counter Divide Select 1 (CR0)	Receive Data Register Full (RDRF)
1	Data Bit 1	Data Bit 1	Counter Divide Select 2 (CR1)	Transmit Data Register Empty (TDRE)
2	Data Bit 2	Data Bit 2	Word Select 1 (CR2)	$\overline{\text{Data Carrier Detect}}$ ($\overline{DCD}$)
3	Data Bit 3	Data Bit 3	Word Select 2 (CR3)	$\overline{\text{Clear to Send}}$ ($\overline{CTS}$)
4	Data Bit 4	Data Bit 4	Word Select 3 (CR4)	Framing Error (FE)
5	Data Bit 5	Data Bit 5	Transmit Control 1 (CR5)	Receiver Overrun (OVRN)
6	Data Bit 6	Data Bit 6	Transmit Control 2 (CR6)	Parity Error (PE)
7	Data Bit 7***	Data Bit 7**	Receive Interrupt Enable (CR7)	Interrupt Request (IRQ)

* Leading bit = LSB = Bit 0
** Data bit will be zero in 7 bit plus parity modes.
*** Data bit is "don't care" in 7 bit plus parity modes.

the data is retained in the RDR. The status is maintained by RDRF as to whether or not the data is current. When the Receive Data Register is full, the automatic transfer of data from the Receiver Shift Register to the Data Register is inhibited and the RDR contents remain valid with its current status stored in the Status Register.

CONTROL REGISTER

The ACIA Control Register consists of eight bits of write-only buffer that are selected when RS and R/W are low. This register controls the function of the receiver, transmitter, interrupt enables, and the $\overline{\text{Request-to-Send}}$ peripheral/modem control output.

Counter Divide Select Bits (CR0 and CR1) – The Counter Divide Select Bits (CR0 and CR1) determine the divide ratios utilized in both the transmitter and receiver sections of the ACIA. Additionally, these bits are used to provide a master reset for the ACIA which clears the Status Register (except for external conditions on $\overline{CTS}$ and $\overline{DCD}$) and initializes both the receiver and transmitter. Master reset does not affect other Control Register bits. Note that after power-on or a power fail/restart, these bits must be set high to reset the ACIA. After reseting, the clock divide ratio may be selected. These counter select bits provide for the following clock divide ratios:

CR1	CR0	Function
0	0	÷ 1
0	1	÷ 16
1	0	÷ 64
1	1	Master Reset

Word Select Bits (CR2, CR3, and CR4) – The Word Select bits are used to select word length, parity, and the number of stop bits. The encoding format is as follows:

CR4	CR3	CR2	Function
0	0	0	7 Bits + Even Parity + 2 Stop Bits
0	0	1	7 Bits + Odd Parity + 2 Stop Bits
0	1	0	7 Bits + Even Parity + 1 Stop Bit
0	1	1	7 Bits + Odd Parity + 1 Stop Bit
1	0	0	8 Bits + 2 Stop Bits
1	0	1	8 Bits + 1 Stop Bit
1	1	0	8 Bits + Even Parity + 1 Stop Bit
1	1	1	8 Bits + Odd Parity + 1 Stop Bit

Word length, Parity Select, and Stop Bit changes are not buffered and therefore become effective immediately.

Transmitter Control Bits (CR5 and CR6) – Two Transmitter Control bits provide for the control of the interrupt from the Transmit Data Register Empty condition, the $\overline{\text{Request-to-Send}}$ ($\overline{RTS}$) output, and the transmission of a Break level (space). The following encoding format is used:

CR6	CR5	Function
0	0	$\overline{RTS}$ = low, Transmitting Interrupt Disabled.
0	1	$\overline{RTS}$ = low, Transmitting Interrupt Enabled.
1	0	$\overline{RTS}$ = high, Transmitting Interrupt Disabled.
1	1	$\overline{RTS}$ = low, Transmits a Break level on the Transmit Data Output. Transmitting Interrupt Disabled.

Receive Interrupt Enable Bit (CR7) – The following interrupts will be enabled by a high level in bit position 7 of the Control Register (CR7): Receive Data Register Full, Overrun, or a low to high transistion on the $\overline{\text{Data Carrier Detect}}$ ($\overline{DCD}$) signal line.

MC6850

STATUS REGISTER

Information on the status of the ACIA is available to the MPU by reading the ACIA Status Register. This read-only register is selected when RS is low and R/W is high. Information stored in this register indicates the status of the Transmit Data Register, the Receive Data Register and error logic, and the peripheral/modem status inputs of the ACIA.

Receive Data Register Full (RDRF), Bit 0 – Receive Data Register Full indicates that received data has been transferred to the Receive Data Register. RDRF is cleared after an MPU read of the Receive Data Register or by a master reset. The cleared or empty state indicates that the contents of the Receive Data Register are not current. $\overline{\text{Data Carrier Detect}}$ being high also causes RDRF to indicate empty.

Transmit Data Register Empty (TDRE), Bit 1 – The Transmit Data Register Empty bit being set high indicates that the Transmit Data Register contents have been transferred and that new data may be entered. The low state indicates that the register is full and that transmission of a new character has not begun since the last write data command.

$\overline{\text{Data Carrier Detect}}$ ($\overline{\text{DCD}}$), Bit 2 – The $\overline{\text{Data Carrier Detect}}$ bit will be high when the $\overline{\text{DCD}}$ input from a modem has gone high to indicate that a carrier is not present. This bit going high causes an Interrupt Request to be generated when the Receive Interrupt Enable is set. It remains high after the $\overline{\text{DCD}}$ input is returned low until cleared by first reading the Status Register and then the Data Register or until a master reset occurs. If the $\overline{\text{DCD}}$ input remains high after read status and read data or master reset has occurred, the interrupt is cleared, the $\overline{\text{DCD}}$ status bit remains high and will follow the $\overline{\text{DCD}}$ input.

$\overline{\text{Clear-to-Send}}$ ($\overline{\text{CTS}}$), Bit 3 – The $\overline{\text{Clear-to-Send}}$ bit indicates the state of the $\overline{\text{Clear-to-Send}}$ input from a modem. A low $\overline{\text{CTS}}$ indicates that there is a $\overline{\text{Clear-to-Send}}$ from the modem. In the high state, the Transmit Data Register Empty bit is inhibited and the $\overline{\text{Clear-to-Send}}$ status bit will be high. Master reset does not affect the $\overline{\text{Clear-to-Send}}$ Status bit.

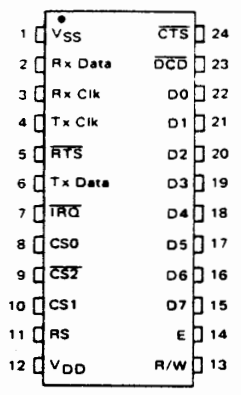
Framing Error (FE), Bit 4 – Framing error indicates that the received character is improperly framed by a start and a stop bit and is detected by the absence of the 1st stop bit. This error indicates a synchronization error, faulty transmission, or a break condition. The framing error flag is set or reset during the receive data transfer time. Therefore, this error indicator is present throughout the time that the associated character is available.

Receiver Overrun (OVRN), Bit 5 – Overrun is an error flag that indicates that one or more characters in the data stream were lost. That is, a character or a number of characters were received but not read from the Receive Data Register (RDR) prior to subsequent characters being received. The overrun condition begins at the midpoint of the last bit of the second character received in succession without a read of the RDR having occurred. The Overrun does not occur in the Status Register until the valid character prior to Overrun has been read. The RDRF bit remains set until the Overrun is reset. Character synchronization is maintained during the Overrun condition. The Overrun indication is reset after the reading of data from the Receive Data Register or by a Master Reset.

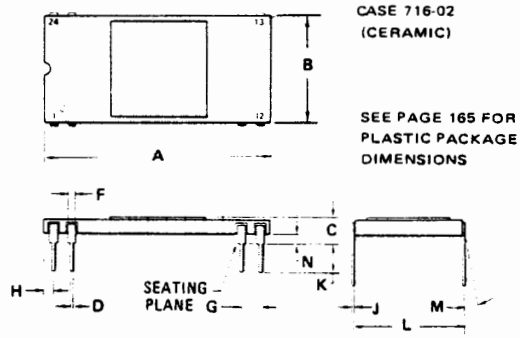
Parity Error (PE), Bit 6 – The parity error flag indicates that the number of highs (ones) in the character does not agree with the preselected odd or even parity. Odd parity is defined to be when the total number of ones is odd. The parity error indication will be present as long as the data character is in the RDR. If no parity is selected, then both the transmitter parity generator output and the receiver parity check results are inhibited.

Interrupt Request (IRQ), Bit 7 – The IRQ bit indicates the state of the $\overline{\text{IRQ}}$ output. Any interrupt condition with its applicable enable will be indicated in this status bit. Anytime the $\overline{\text{IRQ}}$ output is low the IRQ bit will be high to indicate the interrupt or service request status. IRQ is cleared by a read operation to the Receive Data Register or a write operation to the Transmit Data Register.

PIN ASSIGNMENT



PACKAGE DIMENSIONS



CASE 716-02
(CERAMIC)

SEE PAGE 165 FOR PLASTIC PACKAGE DIMENSIONS

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	29.97	30.99	1.180	1.220
B	14.88	15.62	0.585	0.615
C	3.05	4.19	0.120	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.40	0.030	0.055
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.30	0.008	0.012
K	2.54	4.19	0.100	0.165
L	14.88	15.37	0.585	0.605
M	–	10°	–	10°
N	0.51	1.52	0.020	0.060

NOTE:
1. LEADS TRUE POSITIONED WITHIN 0.25mm (0.010) DIA (AT SEATING PLANE) AT MAXIMUM MATERIAL CONDITION.

MOTOROLA Semiconductors
BOX 20912 • PHOENIX, ARIZONA 85036

MCM6810A

(0 to 70°C; L or P Suffix)

MCM6810AC

(-40 to 85°C; L Suffix only)

MOS

(N-CHANNEL, SILICON-GATE)

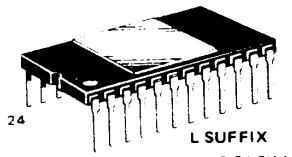
128 X 8-BIT STATIC RANDOM ACCESS MEMORY

128 X 8-BIT STATIC RANDOM ACCESS MEMORY

The MCM6810 is a byte-organized memory designed for use in bus-organized systems. It is fabricated with N-channel silicon-gate technology. For ease of use, the device operates from a single power supply, has compatibility with TTL and DTL, and needs no clocks or refreshing because of static operation.

The memory is compatible with the M6800 Microcomputer Family, providing random storage in byte increments. Memory expansion is provided through multiple Chip Select inputs.

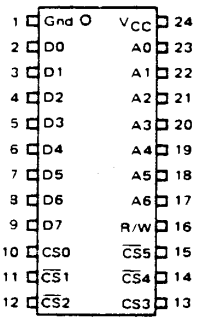
- Organized as 128 Bytes of 8 Bits
- Static Operation
- Bi-Directional Three-State Data Input/Output
- Six Chip Select Inputs (Four Active Low, Two Active High)
- Single 5-Volt Power Supply
- TTL Compatible
- Maximum Access Time = 350 ns – MCM6810AL1
  450 ns – MCM6810AL



L SUFFIX
CERAMIC PACKAGE
CASE 716

P SUFFIX
PLASTIC PACKAGE
CASE 709
NOT SHOWN

PIN ASSIGNMENT

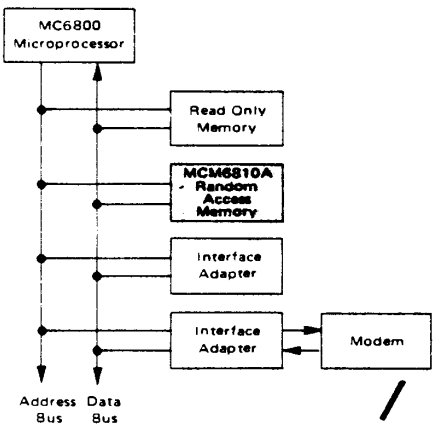


ABSOLUTE MAXIMUM RATINGS (See Note 1)

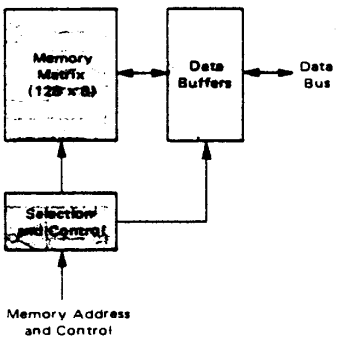
Rating	Symbol	Value	Unit
Supply Voltage	V_{CC}	-0.3 to +7.0	Vdc
Input Voltage	V_{in}	-0.3 to +7.0	Vdc
Operating Temperature Range	T_A	0 to +70	°C
Storage Temperature Range	T_{stg}	-65 to +150	°C

NOTE 1. Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

M6800 MICROCOMPUTER FAMILY BLOCK DIAGRAM



MCM6810A RANDOM ACCESS MEMORY BLOCK DIAGRAM



MCM6810A

DC OPERATING CONDITIONS AND CHARACTERISTICS

(Full operating voltage and temperature range unless otherwise noted.)

RECOMMENDED DC OPERATING CONDITIONS

Parameter	Symbol	Min	Nom	Max	Unit
Supply Voltage	V_{CC}	4.75	5.0	5.25	Vdc
Input High Voltage	V_{IH}	2.0	–	5.25	Vdc
Input Low Voltage	V_{IL}	-0.3	–	0.8	Vdc

DC CHARACTERISTICS

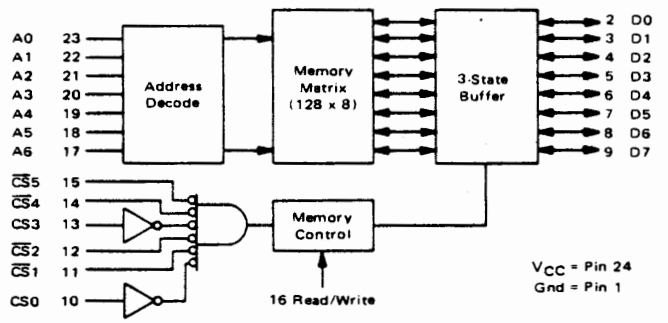
Characteristic	Symbol	Min	Typ	Max	Unit
Input Current (A_n, R/W, CS_n, $\overline{CS_n}$) (V_{in} = 0 to 5.25 V)	I_{in}	–	–	2.5	μAdc
Output High Voltage (I_{OH} = -205 μA)	V_{OH}	2.4	–	–	Vdc
Output Low Voltage (I_{OL} = 1.6 mA)	V_{OL}	–	–	0.4	Vdc
Output Leakage Current (Three-State) (CS = 0.8 V or $\overline{CS}$ = 2.0 V, V_{out} = 0.4 V to 2.4 V)	I_{LO}	–	–	10	μAdc
Supply Current (V_{CC} = 5.25 V, all other pins grounded, T_A = 0°C) MCM6810AL MCM6810AL1	I_{CC}	– –	– –	70 80	mAdc

CAPACITANCE (f = 1.0 MHz, T_A = 25°C, periodically sampled rather than 100% tested.)

Characteristic	Symbol	Max	Unit
Input Capacitance	C_{in}	7.5	pF
Output Capacitance	C_{out}	12.5	pF

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

BLOCK DIAGRAM



MCM6810A

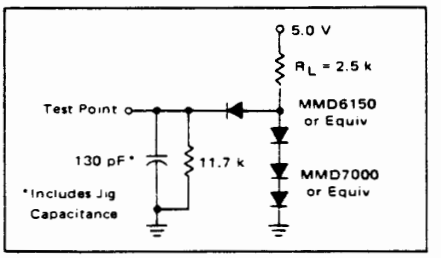
AC OPERATING CONDITIONS AND CHARACTERISTICS

(Full operating voltage and temperature unless otherwise noted.)

AC TEST CONDITIONS

Condition	Value
Input Pulse Levels	0.8 V to 2.0 V
Input Rise and Fall Times	20 ns
Output Load	See Figure 1

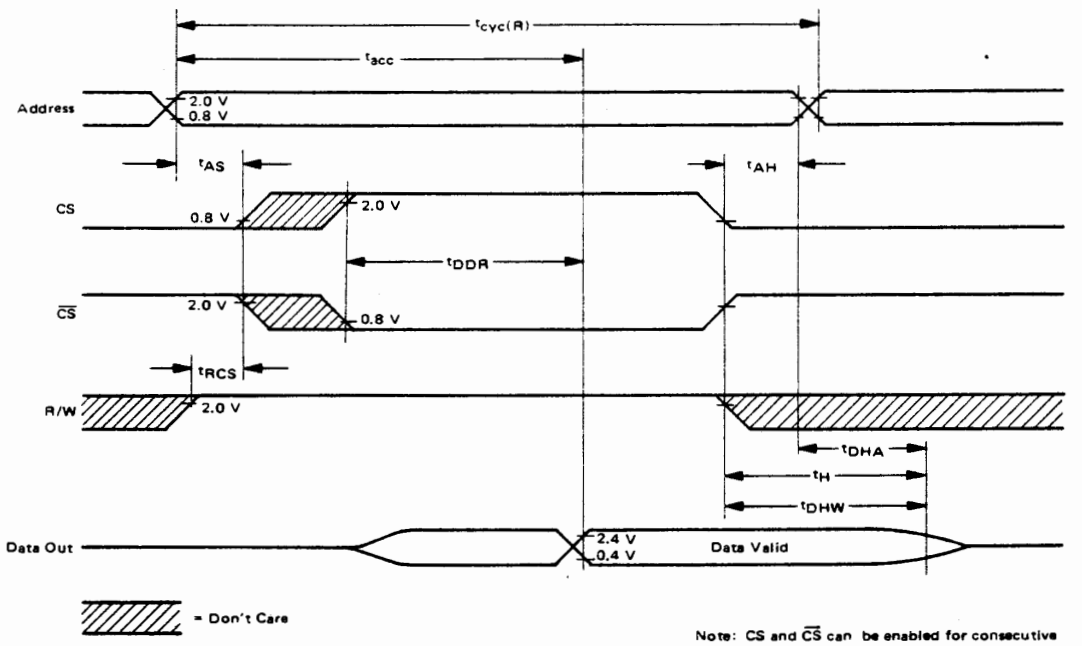
FIGURE 1 – AC TEST LOAD



READ CYCLE

Characteristic	Symbol	MCM6810AL		MCM6810AL1		Unit
		Min	Max	Min	Max	
Read Cycle Time	$t_{cyc(R)}$	450	–	350	–	ns
Access Time	t_{acc}	–	450	–	350	ns
Address Setup Time	t_{AS}	20	–	20	–	ns
Address Hold Time	t_{AH}	0	–	0	–	ns
Data Delay Time (Read)	t_{DDR}	–	230	–	180	ns
Read to Select Delay Time	t_{RCS}	0	–	0	–	ns
Data Hold from Address	t_{DHA}	10	–	10	–	ns
Output Hold Time	t_H	10	–	10	–	ns
Data Hold from Write	t_{DHW}	10	80	10	60	ns

READ CYCLE TIMING



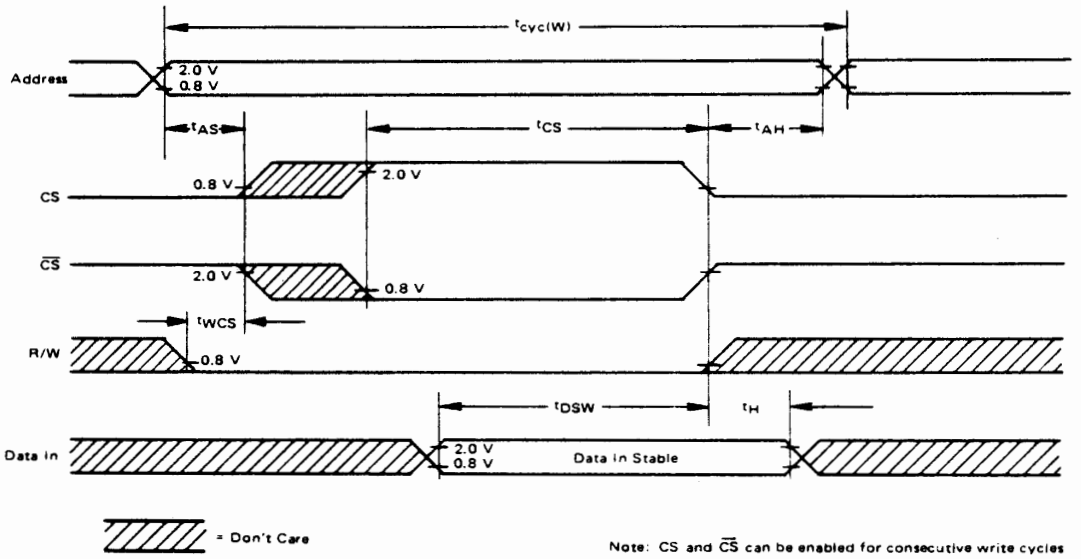
Note: CS and $\overline{CS}$ can be enabled for consecutive read cycles provided R/W remains at V_{IH}.

MCM6810A

WRITE CYCLE

Characteristic	Symbol	MCM6810AL		MCM6810AL1		Unit
		Min	Max	Min	Max	
Write Cycle Time	$t_{cyc(W)}$	450	–	350	–	ns
Address Setup Time	t_{AS}	20	–	20	–	ns
Address Hold Time	t_{AH}	0	–	0	–	ns
Chip Select Pulse Width	t_{CS}	300	–	250	–	ns
Write to Chip Select Delay Time	t_{WCS}	0	–	0	–	ns
Data Setup Time (Write)	t_{DSW}	190	–	150	–	ns
Input Hold Time	t_H	10	–	10	–	ns

WRITE CYCLE TIMING

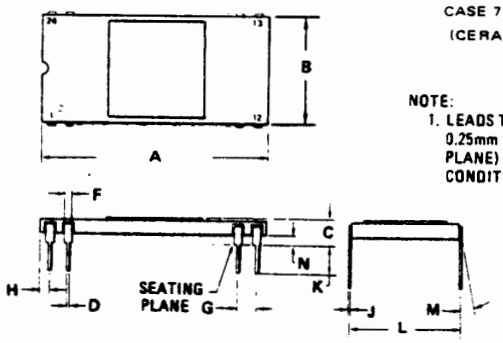


= Don't Care

Note: CS and $\overline{CS}$ can be enabled for consecutive write cycles provided R/W is strobed to V_{IH} before or coincident with the Address change, and remains high for time t_{AS}.

PACKAGE DIMENSIONS

CASE 716-02
(CERAMIC)



NOTE:
1. LEADS TRUE POSITIONED WITHIN 0.25mm (0.010) DIA (AT SEATING PLANE) AT MAXIMUM MATERIAL CONDITION.

See Page 165 for Plastic Package dimensions.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	29.97	30.99	1.180	1.220
B	14.88	15.62	0.585	0.615
C	3.05	4.19	0.120	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.40	0.030	0.055
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.30	0.008	0.012
K	2.54	4.19	0.100	0.165
L	14.88	15.37	0.585	0.605
M	–	10^0	–	10^0
N	0.51	1.52	0.020	0.060

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MCM6830A

Advance Information

MOS

(N-CHANNEL, SILICON-GATE)

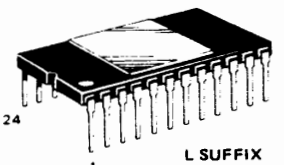
1024 X 8-BIT
READ ONLY MEMORY

1024 X 8-BIT READ ONLY MEMORY

The MCM6830A is a mask-programmable byte-organized memory designed for use in bus-organized systems. It is fabricated with N-channel silicon-gate technology. For ease of use, the device operates from a single power supply, has compatibility with TTL and DTL, and needs no clocks or refreshing because of static operation.

The memory is compatible with the M6800 Microcomputer Family, providing read only storage in byte increments. Memory expansion is provided through multiple Chip Select inputs. The active level of the Chip Select inputs and the memory content are defined by the customer.

- Organized as 1024 Bytes of 8 Bits
- Static Operation
- Three-State Data Output
- Four Chip Select Inputs (Programmable)
- Single 5-Volt Power Supply
- TTL Compatible
- Maximum Access Time = 500 ns



L SUFFIX
CERAMIC PACKAGE
CASE 716

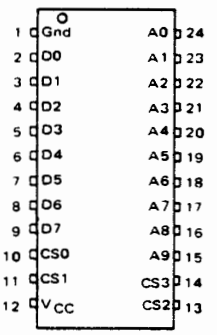
NOT SHOWN: P SUFFIX
PLASTIC PACKAGE
CASE 709

ABSOLUTE MAXIMUM RATINGS (See Note 1)

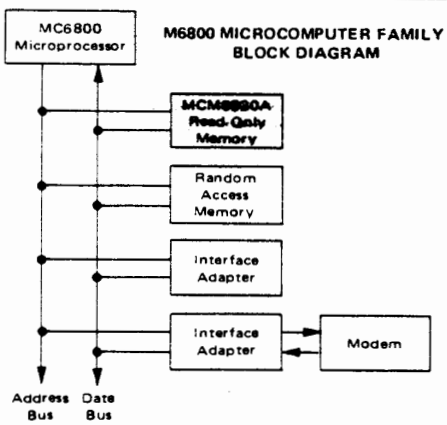
Rating	Symbol	Value	Unit
Supply Voltage	V_{CC}	-0.3 to +7.0	Vdc
Input Voltage	V_{in}	-0.3 to +7.0	Vdc
Operating Temperature Range	T_A	0 to +70	°C
Storage Temperature Range	T_{stg}	-65 to +150	°C

NOTE 1 Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

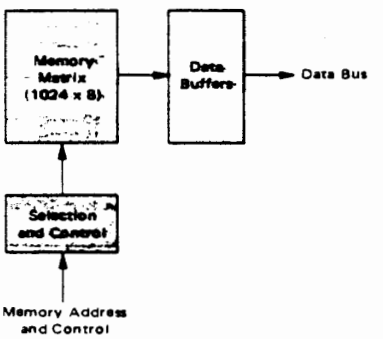
PIN ASSIGNMENT



M6800 MICROCOMPUTER FAMILY BLOCK DIAGRAM



MCM6830A READ ONLY MEMORY BLOCK DIAGRAM



This is advance information and specifications are subject to change without notice.

MCM6830A

DC OPERATING CONDITIONS AND CHARACTERISTICS

(Full operating voltage and temperature range unless otherwise noted.)

RECOMMENDED DC OPERATING CONDITIONS

Parameter	Symbol	Min	Nom	Max	Unit
Supply Voltage	V_{CC}	4.75	5.0	5.25	Vdc
Input High Voltage	V_{IH}	2.0	–	5.25	Vdc
Input Low Voltage	V_{IL}	-0.3	–	0.8	Vdc

DC CHARACTERISTICS

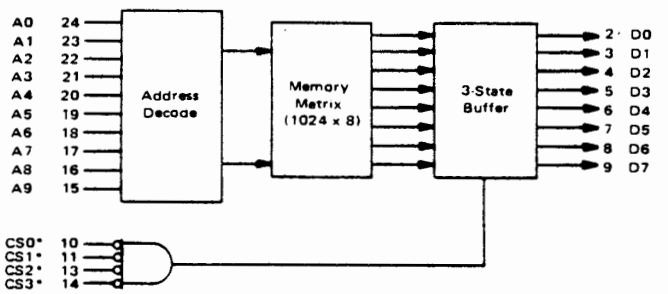
Characteristic	Symbol	Min	Typ	Max	Unit
Input Current (V_{in} = 0 to 5.25 V)	I_{in}	–	–	2.5	μAdc
Output High Voltage (I_{OH} = −205μA)	V_{OH}	2.4	–	–	Vdc
Output Low Voltage (I_{OL} = 1.6 mA)	V_{OL}	–	–	0.4	Vdc
Output Leakage Current (Three-State) (CS = 0.8 V or $\overline{CS}$ = 2.0 V, V_{out} = 0.4 V to 2.4 V)	I_{LO}	–	–	10	μAdc
Supply Current (V_{CC} = 5.25 V, T_A = 0°C)	I_{CC}	–	–	130	mAdc

CAPACITANCE (f = 1.0 MHz, T_A = 25°C, periodically sampled rather than 100% tested.)

Characteristic	Symbol	Max	Unit
Input Capacitance	C_{in}	7.5	pF
Output Capacitance	C_{out}	12.5	pF

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

BLOCK DIAGRAM



*Active level defined by the customer.

V_{CC} = Pin 12
Gnd = Pin 1

MCM6830A

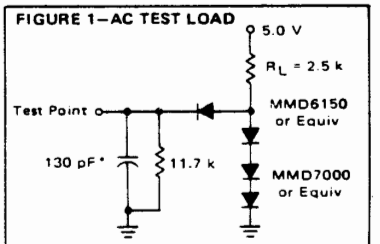
AC OPERATING CONDITIONS AND CHARACTERISTICS

(Full operating voltage and temperature unless otherwise noted.)

(All timing with $t_r = t_f = 20$ ns, Load of Figure 1)

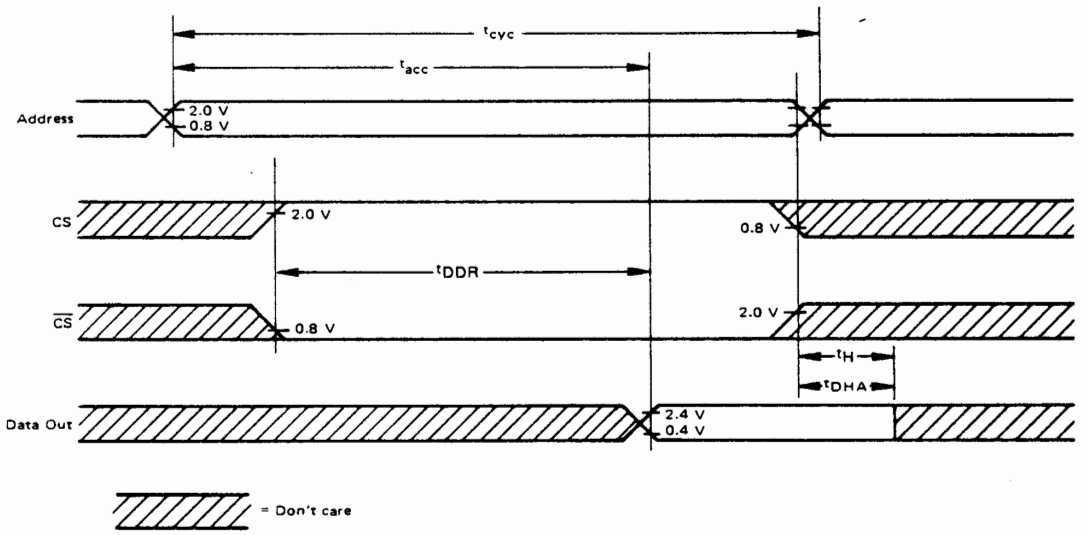
Characteristic	Symbol	Min	Max	Unit
Cycle Time	t_{cyc}	500	–	ns
Access Time	t_{acc}	–	500	ns
Data Delay Time (Read)	t_{DDR}	–	300	ns
Data Hold from Address	t_{DHA}	10	–	ns
Data Hold from Deselection	t_H	10	150	ns

FIGURE 1–AC TEST LOAD



*Includes Jig Capacitance

TIMING DIAGRAM

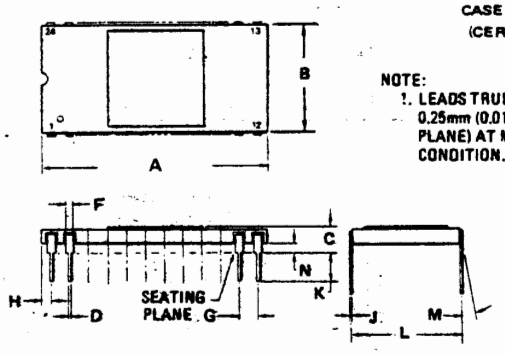


= Don't care

PACKAGE DIMENSIONS

CASE 716-02

(CERAMIC)



NOTE:

1. LEADS TRUE POSITIONED WITHIN 0.25mm (0.010) DIA (AT SEATING PLANE) AT MAXIMUM MATERIAL CONDITION.

See Page 165 for Plastic Package dimensions.

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	29.97	30.99	1.180	1.220
B	14.88	15.62	0.585	0.615
C	3.05	4.19	0.120	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.40	0.030	0.055
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.30	0.008	0.012
K	2.54	4.19	0.100	0.165
L	14.88	15.37	0.585	0.605
M	–	10^0	–	10^0
N	0.51	1.52	0.020	0.060

MCM6830A

CUSTOM PROGRAMMING

By the programming of a single photomask for the MCM6830A, the customer may specify the content of the memory and the method of enabling the outputs.

Information on the general options of the MCM6830A should be submitted on an Organizational Data form such as that shown in Figure 3.

Information for custom memory content may be sent to Motorola in one of two forms (shown in order of preference):

1. Paper tape output of the Motorola M6800 Software.
2. Hexadecimal coding using IBM Punch Cards.

PAPER TAPE

Included in the software packages developed for the M6800 Microcomputer Family is the ability to produce a paper tape output for computerized mask generation. The assembler directives are used to control allocation of memory, to assign values for stored data, and for controlling the assembly process. The paper tape must specify the full 1024 bytes.

Note: Motorola can accept magnetic tape and truth table table formats. For further information, contact your local Motorola sales representative.

FIGURE 2 – BINARY TO HEXADECIMAL CONVERSION

Binary Data				Hexadecimal Character
0	0	0	0	0
0	0	0	1	1
0	0	1	0	2
0	0	1	1	3
0	1	0	0	4
0	1	0	1	5
0	1	1	0	6
0	1	1	1	7
1	0	0	0	8
1	0	0	1	9
1	0	1	0	A
1	0	1	1	B
1	1	0	0	C
1	1	0	1	D
1	1	1	0	E
1	1	1	1	F

IBM PUNCH CARDS

The hexadecimal equivalent (from Figure 2) may be placed on 80 column IBM punch cards as follows:

Step	Column	
1	12	Byte "0" Hexadecimal equivalent for outputs D7 thru D4 (D7 = M.S.B.)
2	13	Byte "0" Hexadecimal equivalent for outputs D3 thru D0 (D3 = M.S.B.)
3	14-75	Alternate steps 1 and 2 for consecutive bytes.
4	77-78	Card number (starting 01)
5	79-80	Total number of cards (32)

FIGURE 3 – FORMAT FOR PROGRAMMING GENERAL OPTIONS

ORGANIZATIONAL DATA
MCM6830A MOS READ ONLY MEMORY

Customer:

Company _____

Part No. _____

Originator _____

Phone No. _____

Motorola Use Only:

Quote: _____

Part No.: _____

Specif. No.: _____

Enable Options:

	1	0
CS0	☐	☐
CS1	☐	☐
CS2	☐	☐
CS3	☐	☐

1 is most positive
0 is most negative

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MCM6832

Advance Information

MOS

(N-CHANNEL, LOW THRESHOLD)

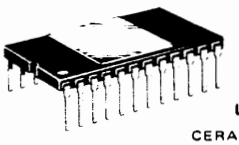
2048 x 8-BIT
READ ONLY MEMORY

2048 x 8-BIT READ ONLY MEMORY

The MCM6832 is a mask-programmable byte-organized memory designed for use in bus-organized systems. It is fabricated with N-channel metal-gate technology. For ease of use, the device is compatible with TTL and DTL, and needs no clocks or refreshing because of static operation.

The memory is compatible with the M6800 Microcomputer Family, providing read only storage in byte increments. Memory expansion is provided through a Chip Select input. The active level of the Chip Select input and the memory content are defined by the customer.

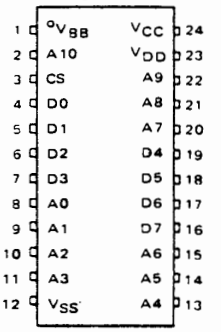
- Organized as 2048 Bytes of 8 Bits
- Static Operation
- Three-State Data Output
- Programmable Chip Select
- TTL Compatible
- Maximum Access Time = 500 ns



L SUFFIX
CERAMIC PACKAGE
CASE 716

NOT SHOWN: P SUFFIX
PLASTIC PACKAGE
CASE 709

PIN ASSIGNMENT

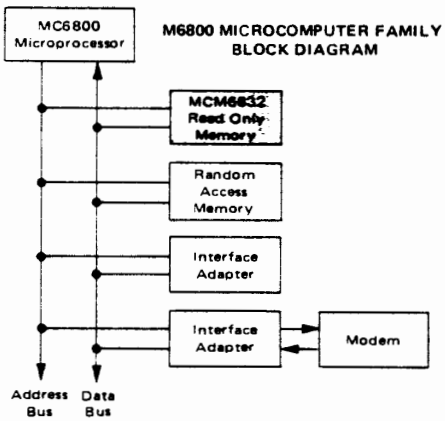


ABSOLUTE MAXIMUM RATINGS[1] (Referenced to V_{SS})

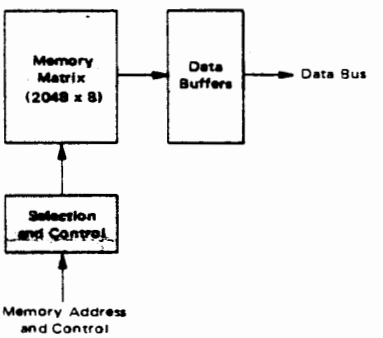
Rating	Symbol	Value	Unit
Supply Voltages	V_{DD} V_{CC} V_{BB}	-0.3 to +15 -0.3 to +6.0 -10 to +0.3	Vdc
Address/Control Input Voltage	V_{in}	-0.3 to +15	Vdc
Operating Temperature Range	T_A	0 to +70	°C
Storage Temperature Range	T_{stg}	-55 to +125	°C

Note 1: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

M6800 MICROCOMPUTER FAMILY
BLOCK DIAGRAM



MCM6832 READ ONLY MEMORY
BLOCK DIAGRAM



This is advance information and specifications are subject to change without notice.

MCM6832

DC OPERATING CONDITIONS AND CHARACTERISTICS

(Full operating voltage and temperature range unless otherwise noted.)

RECOMMENDED DC OPERATING CONDITIONS (Referenced to V_{SS} = Ground)

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage	V_{DD}	11.4	12	12.6	Vdc
	V_{CC}	4.75	5.0	5.25	Vdc
	V_{BB}	-5.25	-5.0	-4.75	Vdc
Input High Voltage (A_n, CS)	V_{IH}	3.0	–	V_{CC}	Vdc
Input Low Voltage (A_n, CS)	V_{IL}	-0.3	–	0.8	Vdc

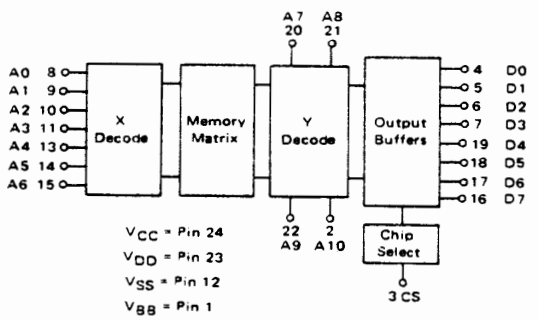
DC CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
Input Leakage Current (A_n, CS) (V_{in} = 0 to 5.25 V)	I_{in}	–	–	10	μAdc
Output Leakage Current (Three-State) (V_O = 0.4 V to -2.4 V, CS = 0.4 V or $\overline{CS}$ = 2.4 V.)	I_{LO}	–	–	10	μAdc
Output High Voltage (I_{OH} = -100 μA)	V_{OH}	3.7	–	V_{CC}	Vdc
Output Low Voltage (I_{OL} = 1.6 mA)	V_{OL}	0	–	0.4	Vdc
Supply Current	I_{DD}	–	–	25	mAdc
(Chip Deselected or Selected)	I_{CC}	–	–	45	mAdc
	I_{BB}	–	–	500	μAdc

CAPACITANCE (Periodically Sampled Rather Than 100% Tested.)

Characteristic	Symbol	Min	Typ	Max	Unit
Input Capacitance (f = 1 MHz)	C_{in}	–	5.0	7.5	pF
Output Capacitance (f = 1 MHz)	C_{out}	–	5.0	10	pF

BLOCK DIAGRAM



MCM6832

AC CHARACTERISTICS

(Full operating voltage and temperature unless otherwise noted. All timing with $t_r = t_f \leq 20$ ns; Load = 1 TTL Gate (MC7400 Series) biased to draw 1.6 mA; C_L = 130 pF.)

Characteristic	Symbol	Min	Typ*	Max	Unit
Address Access Time	t_{acc}	–	320*	500	ns
Output Select Time	t_{OS}	–	175*	300	ns
Output Deselect Time	t_{OD}	30	100*	150	ns

*Typical values measured at 25°C and nominal supply voltages.

FIGURE 1 – AC TEST LOAD

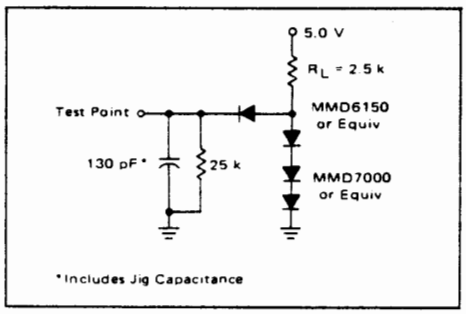
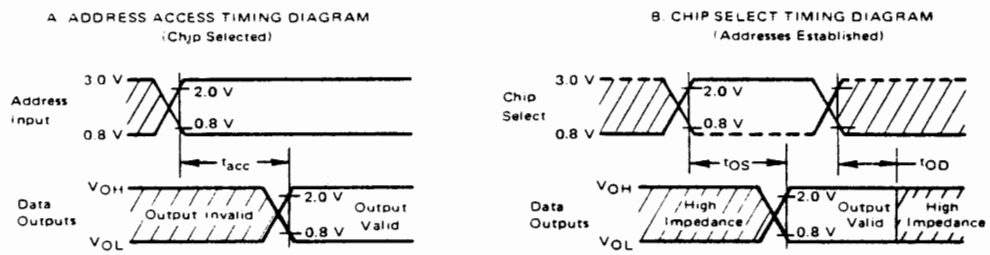
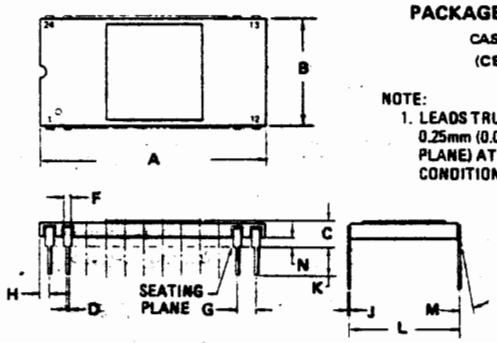


FIGURE 2 – TIMING DIAGRAM



PACKAGE DIMENSIONS

CASE 716-02
(CERAMIC)



NOTE:
1. LEADS TRUE POSITIONED WITHIN 0.25mm (0.010) DIA (AT SEATING PLANE) AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	29.97	30.99	1.180	1.220
B	14.88	15.62	0.585	0.615
C	3.05	4.19	0.120	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.40	0.030	0.055
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.30	0.008	0.012
K	2.54	4.19	0.100	0.165
L	14.88	15.37	0.585	0.605
M	–	10^0	–	10^0
N	0.51	1.52	0.020	0.060

SEE PAGE 165 FOR PLASTIC PACKAGE DIMENSIONS.

MCM6832

CUSTOM PROGRAMMING

By the programming of a single photomask for the MCM6832, the customer may specify the content of the memory and the method of enabling the outputs.

Information on the general options of the MCM6832 should be submitted on an Organizational Data form such as that shown in Figure 4.

Information for custom memory content may be sent to Motorola in one of two forms (shown in order of preference):

1. Paper tape output of the Motorola M6800 Software.
2. Hexadecimal coding using IBM Punch Cards.

PAPER TAPE

Included in the software packages developed for the M6800 Microcomputer Family is the ability to produce a paper tape output for computerized mask generation. The assembler directives are used to control allocation of memory, to assign values for stored data, and for controlling the assembly process. The paper tape must specify the full 2048 bytes.

Note: Motorola can accept magnetic tape and truth table table formats. For further information, contact your local Motorola sales representative.

FIGURE 3 – BINARY TO HEXADECIMAL CONVERSION

MSB D7 D3	D6 D2	D5 D1	LSB D4 D0	Hexadecimal Character
0	0	0	0	0
0	0	0	1	1
0	0	1	0	2
0	0	1	1	3
0	1	0	0	4
0	1	0	1	5
0	1	1	0	6
0	1	1	1	7
1	0	0	0	8
1	0	0	1	9
1	0	1	0	A
1	0	1	1	B
1	1	0	0	C
1	1	0	1	D
1	1	1	0	E
1	1	1	1	F

$0 = V_{OL}$
$1 = V_{OH}$

IBM PUNCH CARDS

The hexadecimal equivalent (from Figure 3) may be placed on 80 column IBM punch cards as follows:

Step	Column	
1	12	Byte "0" Hexadecimal equivalent for outputs D7 thru D4 (D7 = M.S.B.)
2	13	Byte "0" Hexadecimal equivalent for outputs D3 thru D0 (D3 = M.S.B.)
3	14-75	Alternate steps 1 and 2 for consecutive bytes.
4	77-78	Card number (starting 01)
5	79-80	Total number of cards (64)

FIGURE 4 – FORMAT FOR PROGRAMMING GENERAL OPTIONS

ORGANIZATIONAL DATA
MCM6832 MOS READ ONLY MEMORY

Customer:

Company _____

Part No. _____

Originator _____

Phone No. _____

Motorola Use Only

Quote _____

Part No. _____

Specif. No. _____

True Chip Select Options:

I. 1 ☐

II. 0 ☐

1 is most positive
0 is most negative

POSITIVE POWERS OF 2

n	2^n
0	1
1	2
2	4
3	8
4	16
5	32
6	64
7	128
8	256
9	512
10	1024
11	2048
12	4096
13	8192
14	16384
15	32768
16	65536
17	13107 2
18	26214 4
19	52428 8
20	10485 76
21	20971 52
22	41943 04
23	83886 08
24	16777 216
25	33554 432
26	67108 864
27	13421 7728
28	26843 5456
29	53687 0912
30	10737 41824
31	21474 83648
32	42949 67296

NEGATIVE POWERS OF 2

n	2^{-n}
0	1.0
1	0.5
2	0.25
3	0.125
4	0.0625
5	0.03125
6	0.01562 5
7	0.00781 25
8	0.00390 625
9	0.00195 3125
10	0.00097 65625
11	0.00048 82812 5
12	0.00024 41406 25
13	0.00012 20703 125
14	0.00006 10351 5625
15	0.00003 05175 78125
16	0.00001 52587 89062 5
17	0.00000 76293 94531 25
18	0.00000 38146 97265 625
19	0.00000 19073 48632 8125
20	0.00000 09536 74316 40625
21	0.00000 04768 37158 20312 5
22	0.00000 02384 18579 10156 25
23	0.00000 01192 09289 55078 125
24	0.00000 00596 04644 77539 0625
25	0.00000 00298 02322 38769 53125
26	0.00000 00149 01161 19384 76562 5
27	0.00000 00074 50580 59692 38281 25
28	0.00000 00037 25290 29846 19140 625
29	0.00000 00018 62645 14923 09570 3125
30	0.00000 00009 31322 57461 54785 15625
31	0.00000 00004 65661 28730 77392 57812 5
32	0.00000 00002 32830 64365 38696 28906 25

POSITIVE POWERS OF 8

n	8^n
0	1
1	8
2	64
3	512
4	409 6
5	327 68
6	262 144
7	209 715 2
8	167 772 16

POSITIVE POWERS OF 16

n	16^n
0	1
1	16
2	256
3	409 6
4	655 36
5	104 857 6
6	167 772 16
7	268 435 456
8	429 496 729 6

NEGATIVE POWERS OF 16

n	16^{-n}
0	1.0
1	0.062 5
2	0.003 906 25
3	0.000 244 140 625
4	0.000 015 258 789 062 5